

DRAFT DRA PAR LPC1759/58/56/54/52/51

DRAFT DRAFT 32-bit ARM Cortex-M3 MCU; up to 512 kB flash and 64 kB SRAM with Ethernet, USB 2.0 Host/Device/OTG, CAN

Rev. 03.03 — 4 January 2010

Product data sheet

General description 1.

The LPC1759/58/56/54/52/51 are ARM Cortex-M3 based microcontrollers for embedded applications featuring a high level of integration and low power consumption. The ARM Cortex-M3 is a next generation core that offers system enhancements such as enhanced debug features and a higher level of support block integration.

The LPC1758/56/57/54/52/51 operate at CPU frequencies of up to 100 MHz. The LPC1759 operates at CPU frequencies of up to 120 MHz. The ARM Cortex-M3 CPU incorporates a 3-stage pipeline and uses a Harvard architecture with separate local instruction and data buses as well as a third bus for peripherals. The ARM Cortex-M3 CPU also includes an internal prefetch unit that supports speculative branching.

The peripheral complement of the LPC1759/58/56/54/52/51 includes up to 512 kB of flash memory, up to 64 kB of data memory, Ethernet MAC, USB Device/Host/OTG interface, 8-channel general purpose DMA controller, 4 UARTs, 2 CAN channels, 2 SSP controllers, SPI interface, 2 I²C-bus interfaces, 2-input plus 2-output I²S-bus interface, 6 channel 12-bit ADC, 10-bit DAC, motor control PWM, Quadrature Encoder interface, 4 general purpose timers, 6-output general purpose PWM, ultra-low power Real-Time Clock (RTC) with separate battery supply, and up to 52 general purpose I/O pins.

2. **Features**

- ARM Cortex-M3 processor, running at frequencies of up to 100 MHz (LPC1758/56/57/54/52/51) or of up to 120 MHz (LPC1759). A Memory Protection Unit (MPU) supporting eight regions is included.
- ARM Cortex-M3 built-in Nested Vectored Interrupt Controller (NVIC).
- Up to 512 kB on-chip flash programming memory. Enhanced flash memory accelerator enables high-speed 120 MHz operation with zero wait states.
- In-System Programming (ISP) and In-Application Programming (IAP) via on-chip bootloader software.
- On-chip SRAM includes:
 - Up to 32 kB of SRAM on the CPU with local code/data bus for high-performance CPU access.
 - Two/one 16 kB SRAM blocks with separate access paths for higher throughput. These SRAM blocks may be used for Ethernet (LPC1758 only), USB, and DMA memory, as well as for general purpose CPU instruction and data storage.
- Eight channel General Purpose DMA controller (GPDMA) on the AHB multilayer matrix that can be used with the SSP, I²S-bus, UART, the Analog-to-Digital and Digital-to-Analog converter peripherals, timer match signals, and for memory-to-memory transfers.



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- Multilayer AHB matrix interconnect provides a separate bus for each AHB master. AHB masters include the CPU, General Purpose DMA controller, Ethernet MAC (LPC1758 only), and the USB interface. This interconnect provides communication with no arbitration delays.
- Split APB bus allows high throughput with few stalls between the CPU and DMA.
- Serial interfaces:
 - On the LPC1758 only, Ethernet MAC with RMII interface and dedicated DMA controller.
 - USB 2.0 full-speed device/Host/OTG controller with dedicated DMA controller and on-chip PHY for device, Host, and OTG functions. The LPC1752/51 include a USB device controller only.
 - Four UARTs with fractional baud rate generation, internal FIFO, and DMA support. One UART has modem control I/O and RS-485/EIA-485 support, and one UART has IrDA support.
 - ◆ CAN 2.0B controller with two (LPC1759/58/56) or one (LPC1754/52/51) channels.
 - SPI controller with synchronous, serial, full duplex communication and programmable data length.
 - Two SSP controllers with FIFO and multi-protocol capabilities. The SSP interfaces can be used with the GPDMA controller.
 - Two I²C-bus interfaces supporting fast mode with a data rate of 400 kbit/s with multiple address recognition and monitor mode.
 - On the LPC1759/58/56 only, I²S (Inter-IC Sound) interface for digital audio input or output, with fractional rate control. The I²S-bus interface can be used with the GPDMA. The I²S-bus interface supports 3-wire and 4-wire data transmit and receive as well as master clock input/output.
- Other peripherals:
 - 52 General Purpose I/O (GPIO) pins with configurable pull-up/down resistors. All GPIOs support a new, configurable open-drain operating mode. The GPIO block is accessed through the AHB multilayer bus for fast access and located in memory such that it supports Cortex-M3 bit banding and use by the General Purpose DMA Controller.
 - 12-bit Analog-to-Digital Converter (ADC) with input multiplexing among six pins, conversion rates up to 200 kHz, and multiple result registers. The 12-bit ADC can be used with the GPDMA controller.
 - On the LPC1759/58/56/54 only, 10-bit Digital-to-Analog Converter (DAC) with dedicated conversion timer and DMA support.
 - Four general purpose timers/counters, with a total of three capture inputs and ten compare outputs. Each timer block has an external count input. Specific timer events can be selected to generate DMA requests.
 - One motor control PWM with support for three-phase motor control.
 - Quadrature encoder interface that can monitor one external quadrature encoder.
 - One standard PWM/timer block with external count input.
 - Real-Time Clock (RTC) with a separate power domain and dedicated RTC oscillator. The RTC block includes 20 bytes of battery-powered backup registers.
 - Watchdog Timer (WDT). The WDT can be clocked from the internal RC oscillator, the RTC oscillator, or the APB clock.
 - ARM Cortex-M3 system tick timer, including an external clock input option.

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- Repetitive Interrupt Timer (RIT) provides programmable and repeating timed interrupts.
- Each peripheral has its own clock divider for further power savings.
- Standard JTAG test/debug interface for compatibility with existing tools. Serial Wire Debug and Serial Wire Trace Port options.
- Emulation trace module enables non-intrusive, high-speed real-time tracing of instruction execution.
- Integrated PMU (Power Management Unit) automatically adjusts internal regulators to minimize power consumption during Sleep, Deep sleep, Power-down, and Deep power-down modes.
- Four reduced power modes: Sleep, Deep-sleep, Power-down, and Deep power-down.
- Single 3.3 V power supply (2.4 V to 3.6 V).
- One external interrupt input configurable as edge/level sensitive. All pins on PORT0 and PORT2 can be used as edge sensitive interrupt sources.
- Non-maskable Interrupt (NMI) input.
- The Wakeup Interrupt Controller (WIC) allows the CPU to automatically wake up from any priority interrupt that can occur while the clocks are stopped in deep sleep, power-down, and deep power-down modes.
- Processor wake-up from Power-down mode via any interrupt able to operate during Power-down mode (includes external interrupts, RTC interrupt, USB activity, Ethernet wake-up interrupt (LPC1758 only), CAN bus activity, PORT0/2 pin interrupt, and NMI).
- Brownout detect with separate threshold for interrupt and forced reset.
- Power-On Reset (POR).
- Crystal oscillator with an operating range of 1 MHz to 25 MHz.
- 4 MHz internal RC oscillator trimmed to 1 % accuracy that can optionally be used as a system clock.
- PLL allows CPU operation up to the maximum CPU rate without the need for a high-frequency crystal. May be run from the main oscillator, the internal RC oscillator, or the RTC oscillator.
- USB PLL for added flexibility.
- Code Read Protection (CRP) with different security levels.
- Unique device serial number for identification purposes.
- Available as 80-pin LQFP package (12 mm × 12 mm × 1.4 mm).

3. Applications

- eMetering
- Lighting
- Industrial networking
- Alarm systems
- White goods
- Motor control

Ordering information 4.

NXP Semicon	ductors	LPC1759/58/56/5	LPC1759/58/56/54/52/51			
4. Ordering	a inform	32-bit ARM Cortex-M3 n	nicrocontroller			
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	ng informatio		· 7 _ ·			
Type number	Package Name	Description	Version			
	Package		Version SOT315-1			
Type number	Package Name	Description				
Type number LPC1759FBD80	Package Name LQFP80	Descriptionplastic low-profile quad package; 80 leads; body $12 \times 12 \times 1.4$ mm	SOT315-1			
Type number LPC1759FBD80 LPC1758FBD80 LPC1756FBD80	Package Name LQFP80 LQFP80	Descriptionplastic low-profile quad package; 80 leads; body 12 × 12 × 1.4 mmplastic low-profile quad package; 80 leads; body 12 × 12 × 1.4 mm	SOT315-1 SOT315-1			
Type number LPC1759FBD80 LPC1758FBD80	Package Name LQFP80 LQFP80 LQFP80	Description plastic low-profile quad package; 80 leads; body 12 × 12 × 1.4 mm plastic low-profile quad package; 80 leads; body 12 × 12 × 1.4 mm plastic low-profile quad package; 80 leads; body 12 × 12 × 1.4 mm	SOT315-1 SOT315-1 SOT315-1			

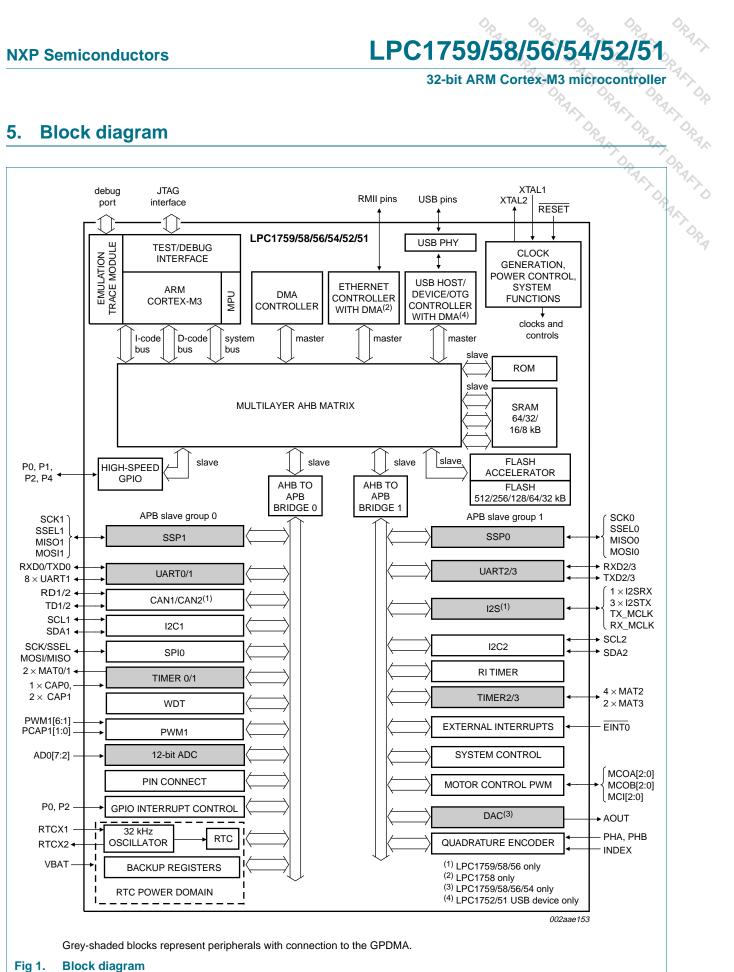
4.1 Ordering options

Table 2. **Ordering options**

Type number	Flash	SRAM	in kB			Ethernet	USB	CAN	l ² S- bus	DAC	Maximum CPU
		CPU	AHB SRAM0	AHB SRAM1	Total						operating frequency
LPC1759FBD80	512 kB	32	16	16	64	no	Device/Host/OTG	2	yes	yes	120 MHz
LPC1758FBD80	512 kB	32	16	16	64	yes	Device/Host/OTG	2	yes	yes	100 MHz
LPC1756FBD80	256 kB	16	16	-	32	no	Device/Host/OTG	2	yes	yes	100 MHz
LPC1754FBD80	128 kB	16	16	-	32	no	Device/Host/OTG	1	no	yes	100 MHz
LPC1752FBD80	64 kB	16	-	-	16	no	Device only	1	no	no	100 MHz
LPC1751FBD80	32 kB	8	-	-	8	no	Device only	1	no	no	100 MHz

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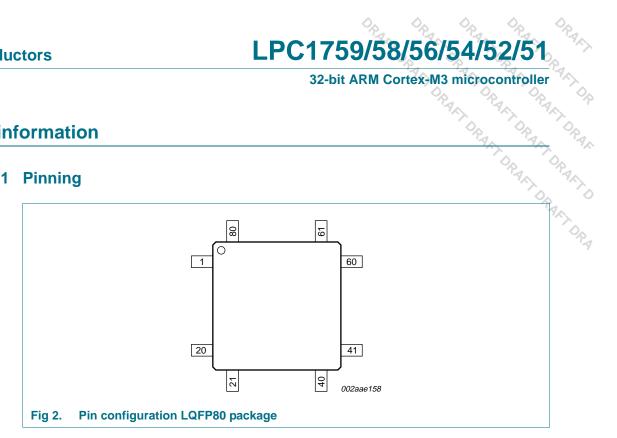
Block diagram 5.



32-bit ARM Cortex-M3 microcontroller

Pinning information 6.

6.1 Pinning



6.2 Pin description

Table 3. Pin des	cription		
Symbol	Pin	Туре	Description
P0[0] to P0[31]		I/O	Port 0: Port 0 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 0 pins depends upon the pin function selected via the pin connect block. Some port pins are not available on the LQFP80 package.
P0[0]/RD1/TXD3/	37 <mark>11</mark>	I/O	P0[0] — General purpose digital input/output pin.
SDA1		I	RD1 — CAN1 receiver input.
		0	TXD3 — Transmitter output for UART3.
		I/O	SDA1 — I^2C1 data input/output (this is not an I^2C -bus compliant open-drain pin).
P0[1]/TD1/RXD3/	38 <mark>[1]</mark>	I/O	P0[1] — General purpose digital input/output pin.
SCL1		0	TD1 — CAN1 transmitter output.
		I	RXD3 — Receiver input for UART3.
		I/O	$SCL1 - I^2C1$ clock input/output (this is not an I ² C-bus compliant open-drain pin).
P0[2]/TXD0/AD0[7]] 79 <mark>[2]</mark>	I/O	P0[2] — General purpose digital input/output pin.
		0	TXD0 — Transmitter output for UART0.
		I	AD0[7] — A/D converter 0, input 7.
P0[3]/RXD0/AD0[6]	80 <mark>[2]</mark>	I/O	P0[3] — General purpose digital input/output pin.
		I	RXD0 — Receiver input for UART0.
		I	AD0[6] — A/D converter 0, input 6.
P0[6]/	64 <mark>11</mark>	I/O	P0[6] — General purpose digital input/output pin.
I2SRX_SDA/ SSEL1/MAT2[0]		I/O	I2SRX_SDA — Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the l^2S -bus specification. (LPC1759/58/56 only).
		I/O	SSEL1 — Slave Select for SSP1.
		0	MAT2[0] — Match output for Timer 2, channel 0.

LPC1759/58/56/54/52/51 32-bit ARM Cortex-M3 microcontroller

			32-bit ARM Cortex-M3 microcontrolle Description
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	description		Pro Pro
Symbol	Pin	Туре	57.
P0[7]/I2STX_CLK/ SCK1/MAT2[1]		I/O	P0[7] — General purpose digital input/output pin.
		I/O	I2STX_CLK — Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the <i>PS-bus specification</i> . (LPC1759/58/56 only).
		I/O	SCK1 — Serial Clock for SSP1.
		0	MAT2[1] — Match output for Timer 2, channel 1.
P0[8]/I2STX_W		I/O	P0[8] — General purpose digital input/output pin.
MISO1/MAT2[2]	2]	I/O	I2STX_WS — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the l^2S -bus specification. (LPC1759/58/56 only).
		I/O	MISO1 — Master In Slave Out for SSP1.
		0	MAT2[2] — Match output for Timer 2, channel 2.
P0[9]/I2STX_SDA/ MOSI1/MAT2[3]		I/O	P0[9] — General purpose digital input/output pin.
	3]	I/O	I2STX_SDA — Transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the l^2S -bus specification. (LPC1759/58/56 only).
		I/O	MOSI1 — Master Out Slave In for SSP1.
		0	MAT2[3] — Match output for Timer 2, channel 3.
P0[10]/TXD2/	39 <mark>[1]</mark>	I/O	P0[10] — General purpose digital input/output pin.
SDA2/MAT3[0]		0	TXD2 — Transmitter output for UART2.
		I/O	SDA2 — I ² C2 data input/output (this is not an open-drain pin).
		0	MAT3[0] — Match output for Timer 3, channel 0.
P0[11]/RXD2/	40 <mark>[1]</mark>	I/O	P0[11] — General purpose digital input/output pin.
SCL2/MAT3[1]		I	RXD2 — Receiver input for UART2.
		I/O	SCL2 — I^2C2 clock input/output (this is not an open-drain pin).
		0	MAT3[1] — Match output for Timer 3, channel 1.
P0[15]/TXD1/	47 <mark>[1]</mark>	I/O	P0[15] — General purpose digital input/output pin.
SCK0/SCK		0	TXD1 — Transmitter output for UART1.
		I/O	SCK0 — Serial clock for SSP0.
		I/O	SCK — Serial clock for SPI.
P0[16]/RXD1/	48 <mark>[1]</mark>	I/O	P0[16] — General purpose digital input/output pin.
SSEL0/SSEL		I	RXD1 — Receiver input for UART1.
		I/O	SSEL0 — Slave Select for SSP0.
		I/O	SSEL — Slave Select for SPI.
P0[17]/CTS1/ MISO0/MISO	46 <mark>[1]</mark>	I/O	P0[17] — General purpose digital input/output pin.
wi300/10130		I	CTS1 — Clear to Send input for UART1.
		I/O	MISO0 — Master In Slave Out for SSP0.
		I/O	MISO — Master In Slave Out for SPI.
P0[18]/DCD1/ MOSI0/MOSI	45 <mark>[1]</mark>	I/O	P0[18] — General purpose digital input/output pin.
		1	DCD1 — Data Carrier Detect input for UART1.
		I/O	MOSI0 — Master Out Slave In for SSP0.

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Table 3.	Findes		continued	Ro Ro
Symbol		Pin	Туре	Description
P0[22]/RTS1/TD1	S1/TD1	44 <u>[1]</u>	I/O	P0[22] — General purpose digital input/output pin.
			0	Description P0[22] — General purpose digital input/output pin. RTS1 — Request to Send output for UART1. Can also be configured to be an RS-485/EIA-485 output enable signal.
		0	TD1 — CAN1 transmitter output.	
P0[25]/AD0[2]/ I2SRX _SDA/ TXD3	7 <mark>[2]</mark>	I/O	P0[25] — General purpose digital input/output pin.	
		Ι	AD0[2] — A/D converter 0, input 2.	
		I/O	I2SRX_SDA — Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the l^2S -bus specification. (LPC1759/58/56 only).	
		0	TXD3 — Transmitter output for UART3.	
P0[26]/AD0		6 <mark>[3]</mark>	I/O	P0[26] — General purpose digital input/output pin.
AOUT/RXD3		I	AD0[3] — A/D converter 0, input 3.	
		0	AOUT — DAC output. (LPC1759/58/56/54 only).	
		I	RXD3 — Receiver input for UART3.	
P0[29]/USB_D+	B_D+	22 <mark>[4]</mark>	I/O	P0[29] — General purpose digital input/output pin.
		I/O	USB_D+ — USB bidirectional D+ line.	
P0[30]/USB_D-	23 <mark>[4]</mark>	I/O	P0[30] — General purpose digital input/output pin.	
		I/O	USB_D- — USB bidirectional D- line.	
P1[0] to P1	[31]		I/O	Port 1: Port 1 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 1 pins depends upon the pin function selected via the pin connect block. Some port pins are not available on the LQFP80 package.
P1[0]/		76 <mark>[1]</mark>	I/O	P1[0] — General purpose digital input/output pin.
ENET_TXI	D0		0	ENET_TXD0 — Ethernet transmit data 0. (LPC1758 only).
P1[1]/		75 <mark>1]</mark>	I/O	P1[1] — General purpose digital input/output pin.
ENET_TXI	D1		0	ENET_TXD1 — Ethernet transmit data 1. (LPC1758 only).
P1[4]/		74 <mark>11</mark>	I/O	P1[4] — General purpose digital input/output pin.
ENET_TX	_EN		0	ENET_TX_EN — Ethernet transmit data enable. (LPC1758 only).
P1[8]/		73 <mark>1]</mark>	I/O	P1[8] — General purpose digital input/output pin.
ENET_CR	S		Ι	ENET_CRS — Ethernet carrier sense. (LPC1758 only).
P1[9]/		72 <mark>1]</mark>	I/O	P1[9] — General purpose digital input/output pin.
ENET_RX	D0		Ι	ENET_RXD0 — Ethernet receive data. (LPC1758 only).
P1[10]/	71[1]	71 <mark>1</mark>	I/O	P1[10] — General purpose digital input/output pin.
ENET_RX	D1		Ι	ENET_RXD1 — Ethernet receive data. (LPC1758 only).
P1[14]/	70[1]	70 <mark>[1]</mark>	I/O	P1[14] — General purpose digital input/output pin.
ENET_RX	_ER			I
P1[15]/		69 <mark>[1]</mark>	I/O	P1[15] — General purpose digital input/output pin.
ENET_RE	F_CLK		1	ENET_REF_CLK — Ethernet reference clock. (LPC1758 only).
P1[18]/		25 <mark>[1]</mark>	I/O	P1[18] — General purpose digital input/output pin.
USB_UP_I PWM1[1]/ CAP1[0]	LED/		0	USB_UP_LED — USB GoodLink LED indicator. It is LOW when device is configured (non-control endpoints enabled). It is HIGH when the device is not configured or during global suspend.
			0	PWM1[1] — Pulse Width Modulator 1, channel 1 output.
				CAP1[0] — Capture input for Timer 1, channel 0.
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ble 3. Pin description continued	Op
/mbol Pin Type Description	
I[19]/MCOA0/ 26 ^[1] I/O P1[19] — General purpose digital input/output pin. SB_PPWR O MCOA0 Meter control RW/M channel 0 output 4	PAL
	<u></u>
O USB_PPWR — Port Power enable signal for USB port. (LPC1759/58/56/54	only).
I CAP1[1] — Capture input for Timer 1, channel 1.	
I[20]/MCI0/ 27 ^[1] I/O P1[20] — General purpose digital input/output pin. NM1[2]/SCK0 McI0 McI0 Motor control PW/M channel 0, input, Also Quadrature Encoder Inte	
MM1[2]/SCK0 I MCI0 — Motor control PWM channel 0, input. Also Quadrature Encoder Inte PHA input.	erface
O PWM1[2] — Pulse Width Modulator 1, channel 2 output.	
I/O SCK0 — Serial clock for SSP0.	
I[22]/MCOB0/ 28 ^[1] I/O P1[22] — General purpose digital input/output pin.	
SB_PWRD/ O MCOB0 — Motor control PWM channel 0, output B. AT1[0]	
I USB_PWRD — Power Status for USB port (host power switch). (LPC1759/58/56/54 only).	
O MAT1[0] — Match output for Timer 1, channel 0.	
I[23]/MCI1/ 29 ^[1] I/O P1[23] — General purpose digital input/output pin.	
MM1[4]/MISO0 I MCI1 — Motor control PWM channel 1, input. Also Quadrature Encoder Interpretence PHB input.	erface
O PWM1[4] — Pulse Width Modulator 1, channel 4 output.	
I/O MISO0 — Master In Slave Out for SSP0.	
I[24]/MCI2/ 30 ^[1] I/O P1[24] — General purpose digital input/output pin.	
MM1[5]/MOSI0 I MCI2 — Motor control PWM channel 2, input. Also Quadrature Encoder Intel INDEX input.	erface
O PWM1[5] — Pulse Width Modulator 1, channel 5 output.	
I/O MOSI0 — Master Out Slave in for SSP0.	
I[25]/MCOA1/ 31 ^[1] I/O P1[25] — General purpose digital input/output pin.	
AT1[1] O MCOA1 — Motor control PWM channel 1, output A.	
O MAT1[1] — Match output for Timer 1, channel 1.	
I[26]/MCOB1/ 32 ^[1] I/O P1[26] — General purpose digital input/output pin.	
MM1[6]/CAP0[0] O MCOB1 — Motor control PWM channel 1, output B.	
O PWM1[6] — Pulse Width Modulator 1, channel 6 output.	
I CAP0[0] — Capture input for Timer 0, channel 0.	
I[28]/MCOA2/ 35 ^[1] I/O P1[28] — General purpose digital input/output pin.	
CAP1[0]/ O MCOA2 — Motor control PWM channel 2, output A. AT0[0]	
I PCAP1[0] — Capture input for PWM1, channel 0.	
O MAT0[0] — Match output for Timer 0, channel 0.	
I[29]/MCOB2/ 36 ^[1] I/O P1[29] — General purpose digital input/output pin.	
CAP1[1]/ O MCOB2 — Motor control PWM channel 2, output B.	
AT0[1] I PCAP1[1] — Capture input for PWM1, channel 1.	
O MAT0[1] — Match output for Timer 0, channel 1.	

			LPC1759/58/56/54/52/51 32-bit ARM Cortex-M3 microcontrolle
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Table 3. Pin o	description	.continued	LPC1759/58/56/54/52/51 32-bit ARM Cortex-M3 microcontrolle Description P1[30] — General purpose digital input/output pin.
Symbol	Pin	Туре	Description P1[30] — General purpose digital input/output pin. V _{BUS} — Monitors the presence of USB bus power. Note: This signal must be HIGH for USB reset to occur. AD0[4] — A/D converter 0, input 4. P1[31] — General purpose digital input/output pin.
P1[30]/V _{BUS} /	18 <mark>2]</mark>	I/O	P1[30] — General purpose digital input/output pin.
AD0[4]		I	V _{BUS} — Monitors the presence of USB bus power.
			Note: This signal must be HIGH for USB reset to occur.
		I	AD0[4] — A/D converter 0, input 4.
P1[31]/SCK1/	17 <mark>[2]</mark>	I/O	P1[31] — General purpose digital input/output pin.
AD0[5]		I/O	SCK1 — Serial Clock for SSP1.
		I	AD0[5] — A/D converter 0, input 5.
P2[0] to P2[31]		I/O	Port 2: Port 2 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 2 pins depends upon the pin function selected via the pin connect block. Some port pins are not available on the LQFP80 package.
P2[0]/PWM1[1]/	60 <mark>[1]</mark>	I/O	P2[0] — General purpose digital input/output pin.
TXD1		0	PWM1[1] — Pulse Width Modulator 1, channel 1 output.
		0	TXD1 — Transmitter output for UART1.
P2[1]/PWM1[2]/	59 <mark>[1]</mark>	I/O	P2[1] — General purpose digital input/output pin.
RXD1		0	PWM1[2] — Pulse Width Modulator 1, channel 2 output.
		I	RXD1 — Receiver input for UART1.
P2[2]/PWM1[3]/	58 <mark>[1]</mark>	I/O	P2[2] — General purpose digital input/output pin.
		0	PWM1[3] — Pulse Width Modulator 1, channel 3 output.
TRACEDATA[3]		I	CTS1 — Clear to Send input for UART1.
		0	TRACEDATA[3] — Trace data, bit 3.
P2[3]/PWM1[4]/	55 <mark>[1]</mark>	I/O	P2[3] — General purpose digital input/output pin.
		0	PWM1[4] — Pulse Width Modulator 1, channel 4 output.
TRACEDATA[2]		I	DCD1 — Data Carrier Detect input for UART1.
		0	TRACEDATA[2] — Trace data, bit 2.
P2[4]/PWM1[5]/	54 <mark>[1]</mark>	I/O	P2[4] — General purpose digital input/output pin.
DSR1/		0	PWM1[5] — Pulse Width Modulator 1, channel 5 output.
TRACEDATA[1]		I	DSR1 — Data Set Ready input for UART1.
		0	TRACEDATA[1] — Trace data, bit 1.
P2[5]/PWM1[6]/	53 <mark>[1]</mark>	I/O	P2[5] — General purpose digital input/output pin.
DTR1/		0	PWM1[6] — Pulse Width Modulator 1, channel 6 output.
FRACEDATA[0]		0	DTR1 — Data Terminal Ready output for UART1. Can also be configured to be an RS-485/EIA-485 output enable signal.
		0	TRACEDATA[0] — Trace data, bit 0.
P2[6]/PCAP1[0]		I/O	P2[6] — General purpose digital input/output pin.
RI1/TRACECLK		I	PCAP1[0] — Capture input for PWM1, channel 0.
		I	RI1 — Ring Indicator input for UART1.
		0	TRACECLK — Trace Clock.
P2[7]/RD2/	51 <mark>[1]</mark>	I/O	P2[7] — General purpose digital input/output pin.
RTS1		I	RD2 — CAN2 receiver input. (LPC1759/58/56 only).
		0	RTS1 — Request to Send output for UART1. Can also be configured to be an RS-485/EIA-485 output enable signal.

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			32-bit ARM Cortex-M3 microcontroller Description P2[8] — General purpose digital input/output pin.
			RAN RAN R.
Table 3. P	'in descripti	ioncontinued	
Symbol	Pin	Туре	Description
P2[8]/TD2/	50 <mark>11</mark>	<u>1]</u> I/O	P2[8] — General purpose digital input/output pin. TD2 — CAN2 transmitter output. (LPC1759/58/56 only). TXD2 — Transmitter output for UART2. P2[9] — General purpose digital input/output pin.
TXD2		0	TD2 — CAN2 transmitter output. (LPC1759/58/56 only).
		0	TXD2 — Transmitter output for UART2.
P2[9]/	49[1]	<u>1]</u> I/O	P2[9] — General purpose digital input/output pin.
USB_CONNI RXD2	ECT/	0	USB_CONNECT — Signal used to switch an external 1.5 k Ω resistor under software control. Used with the SoftConnect USB feature.
		Ι	RXD2 — Receiver input for UART2.
P2[10]/EINT	0/NMI 415	5] I/O	P2[10] — General purpose digital input/output pin.
			Note: LOW on this pin while RESET is LOW forces on-chip bootloader to take over control of the part after a reset.
		I	EINT0 — External interrupt 0 input.
		Ι	NMI — Non-maskable interrupt input.
P4[0] to P4[3	51]	I/O	Port 4: Port 4 is a 32-bit I/O port with individual direction controls for each bit. The operation of port 4 pins depends upon the pin function selected via the pin connect block. Some port pins are not available on the LQFP80 package.
P4[28]/RX_N		<u>1]</u> I/O	P4[28] — General purpose digital input/output pin.
MAT2[0]/TXC		I	RX_MCLK — I ² S receive master clock. (LPC1759/58/56 only).
		0	MAT2[0] — Match output for Timer 2, channel 0.
		0	TXD3 — Transmitter output for UART3.
P4[29]/TX_M		<u>1]</u> I/O	P4[29] — General purpose digital input/output pin.
MAT2[1]/RXE	23	I	TX_MCLK — I ² S transmit master clock. (LPC1759/58/56 only).
		0	MAT2[1] — Match output for Timer 2, channel 1.
		I	RXD3 — Receiver input for UART3.
TDO/SWO	1[1]	0	TDO — Test Data out for JTAG interface.
		0	SWO — Serial wire trace output.
TDI	2[1]	I	TDI — Test Data in for JTAG interface.
TMS/SWDIO) 3 <mark>[1]</mark>	I	TMS — Test Mode Select for JTAG interface.
		I/O	SWDIO — Serial wire debug data input/output.
TRST	4 <u>[1]</u>	l	TRST — Test Reset for JTAG interface.
TCK/SWDCL	LK 5[1]	I	TCK — Test Clock for JTAG interface.
		Ι	SWDCLK — Serial wire clock.
RSTOUT	11	0	RSTOUT — This is a 3.3 V pin. LOW on this pin indicates LPC1759/58/56/54/52/51 being in Reset state.
RESET	14 <mark>[6</mark>]	<u>6]</u> [External reset input: A LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. TTL with hysteresis, 5 V tolerant.
XTAL1	19 <mark>17</mark>	7][8]	Input to the oscillator circuit and internal clock generator circuits.
XTAL2	20[7]	7][8] O	Output from the oscillator amplifier.
RTCX1	13 <mark>/</mark>	1 1	Input to the RTC oscillator circuit.
RTCX2	15 <mark>7</mark>	<u>7]</u> O	Output from the RTC oscillator circuit.
V _{SS}	24, 3 43, 9 66, 7	57,	ground: 0 V reference.

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Table 3.	Pin descriptionca	ontinued	32-bit ARM Cortex-M3 microcontrolle
Symbol	Pin	Туре	Description
V _{SSA}	9	I	analog ground: 0 V reference. This should nominally be the same voltage as V_{SS} , but should be isolated to minimize noise and error.
V _{DD(3V3)}	21, 42, 56, 77	I	3.3 V supply voltage: This is the power supply voltage for the I/O ports.
V _{DD(REG)} (3	3V3) 34, 67	I	3.3 V voltage regulator supply voltage: This is the supply voltage for the on-chip voltage regulator only.
V _{DDA}	8	I	analog 3.3 V pad supply voltage: This should be nominally the same voltage as $V_{DD(3V3)}$ but should be isolated to minimize noise and error. This voltage is used to power the ADC and DAC. This pin should be tied to 3.3 V if the ADC and DAC are not used.
VREFP	10	I	ADC positive reference voltage: This should be nominally the same voltage as V_{DDA} but should be isolated to minimize noise and error. Level on this pin is used as a reference for ADC and DAC. This pin should be tied to 3.3 V if the ADC and DAC are not used.
VREFN	12	I	ADC negative reference voltage: This should be nominally the same voltage as V_{SS} but should be isolated to minimize noise and error. Level on this pin is used as a reference for ADC and DAC.
VBAT	16	I	RTC pin power supply: 3.3 V on this pin supplies the power to the RTC peripheral.

[1] 5 V tolerant pad providing digital I/O functions with TTL levels and hysteresis.

5 V tolerant pad providing digital I/O functions (with TTL levels and hysteresis) and analog input. When configured as a ADC input, [2] digital section of the pad is disabled and the pin is not 5 V tolerant.

5 V tolerant pad providing digital I/O with TTL levels and hysteresis and analog output function. When configured as the DAC output, [3] digital section of the pad is disabled.

Pad provides digital I/O and USB functions. It is designed in accordance with the USB specification, revision 2.0 (Full-speed and [4] Low-speed mode only).

[5] 5 V tolerant pad with 5 ns glitch filter providing digital I/O functions with TTL levels and hysteresis.

[6] 5 V tolerant pad with 20 ns glitch filter providing digital I/O function with TTL levels and hysteresis.

[7] Pad provides special analog functionality.

When the system oscillator is not used, connect XTAL1 and XTAL2 as follows: XTAL1 can be left floating or can be grounded (grounding [8] is preferred to reduce susceptibility to noise). XTAL2 should be left floating.

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7. Functional description

7.1 Architectural overview

AT DRAK The ARM Cortex-M3 includes three AHB-Lite buses: the system bus, the I-code bus, and the D-code bus (see Figure 1). The I-code and D-code core buses are faster than the system bus and are used similarly to Tightly Coupled Memory (TCM) interfaces: one bus dedicated for instruction fetch (I-code) and one bus for data access (D-code). The use of two core buses allows for simultaneous operations if concurrent operations target different devices.

The LPC1759/58/56/54/52/51 use a multi-layer AHB matrix to connect the ARM Cortex-M3 buses and other bus masters to peripherals in a flexible manner that optimizes performance by allowing peripherals that are on different slaves ports of the matrix to be accessed simultaneously by different bus masters.

7.2 ARM Cortex-M3 processor

The ARM Cortex-M3 is a general purpose, 32-bit microprocessor, which offers high performance and very low power consumption. The ARM Cortex-M3 offers many new features, including a Thumb-2 instruction set, low interrupt latency, hardware divide, interruptable/continuable multiple load and store instructions, automatic state save and restore for interrupts, tightly integrated interrupt controller with wakeup interrupt controller, and multiple core buses capable of simultaneous accesses.

Pipeline techniques are employed so that all parts of the processing and memory systems can operate continuously. Typically, while one instruction is being executed, its successor is being decoded, and a third instruction is being fetched from memory.

The ARM Cortex-M3 processor is described in detail in the Cortex-M3 Technical Reference Manual that can be found on official ARM website.

7.3 On-chip flash program memory

The LPC1759/58/56/54/52/51 contain up to 512 kB of on-chip flash memory. A new two-port flash accelerator maximizes performance for use with the two fast AHB-Lite buses.

7.4 On-chip SRAM

The LPC1759/58/56/54/52/51 contain a total of up to 64 kB on-chip static RAM memory. This includes the main 32/16/8 kB SRAM, accessible by the CPU and DMA controller on a higher-speed bus, and up to two additional 16 kB each SRAM blocks situated on a separate slave port on the AHB multilayer matrix.

This architecture allows CPU and DMA accesses to be spread over three separate RAMs that can be accessed simultaneously.

7.5 Memory Protection Unit (MPU)

The LPC1759/58/56/54/52/51 have a Memory Protection Unit (MPU) which can be used to improve the reliability of an embedded system by protecting critical data within the user application.

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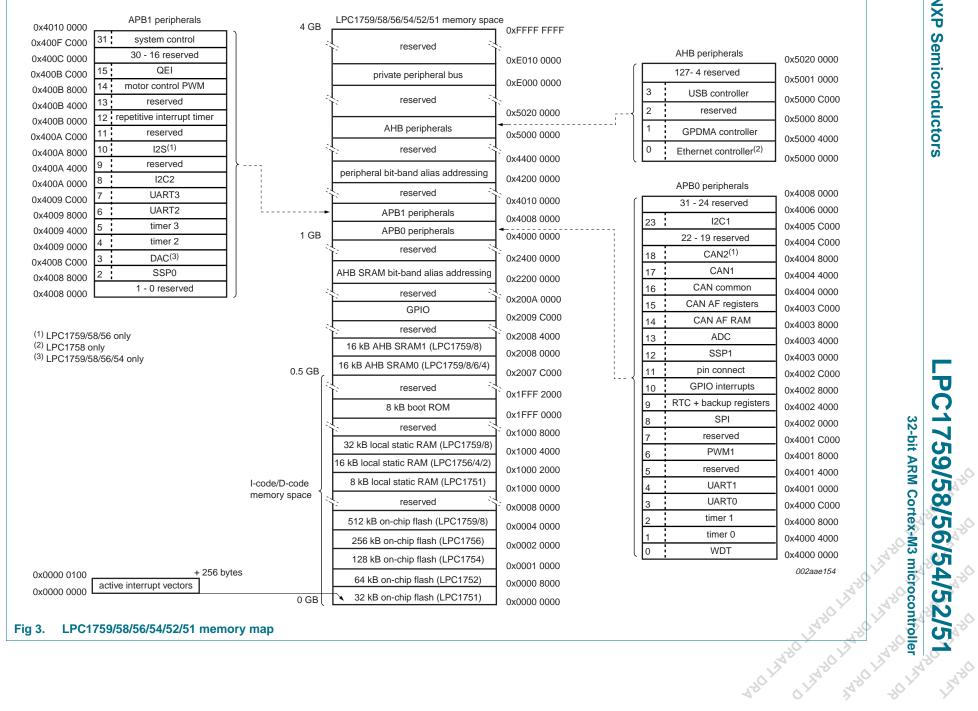
The MPU allows separating processing tasks by disallowing access to each other's data, disabling access to memory regions, allowing memory regions to be defined as read-only and detecting unexpected memory accesses that could potentially break the system.

The MPU separates the memory into distinct regions and implements protection by preventing disallowed accesses. The MPU supports up to 8 regions each of which can be divided into 8 subregions. Accesses to memory locations that are not defined in the MPU regions, or not permitted by the region setting, will cause the Memory Management Fault exception to take place.

7.6 Memory map

The LPC1759/58/56/54/52/51 incorporate several distinct memory regions, shown in the following figures. Figure 3 shows the overall map of the entire address space from the user program viewpoint following reset. The interrupt vector area supports address remapping.

The AHB peripheral area is 2 MB in size, and is divided to allow for up to 128 peripherals. The APB peripheral area is 1 MB in size and is divided to allow for up to 64 peripherals. Each peripheral of either type is allocated 16 kB of space. This allows simplifying the address decoding for each peripheral.



Product data LPC1759_58_56_54_52_51_3 sheet

LPC1759/58/56/54/52/51 memory map Fig 3.

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7.7 Nested Vectored Interrupt Controller (NVIC)

ODRAKT DRAK The NVIC is an integral part of the Cortex-M3. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts. interrupt latency and efficient processing of late arriving interrupts.

7.7.1 Features

- Controls system exceptions and peripheral interrupts
- In the LPC1759/58/56/54/52/51, the NVIC supports 33 vectored interrupts
- 32 programmable interrupt priority levels, with hardware priority level masking
- Relocatable vector table
- Non-Maskable Interrupt (NMI)
- Software interrupt generation

7.7.2 Interrupt sources

Each peripheral device has one interrupt line connected to the NVIC but may have several interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

Any pin on PORT0 and PORT2 (total of 30 pins) regardless of the selected function, can be programmed to generate an interrupt on a rising edge, a falling edge, or both.

7.8 Pin connect block

The pin connect block allows selected pins of the microcontroller to have more than one function. Configuration registers control the multiplexers to allow connection between the pin and the on-chip peripherals.

Peripherals should be connected to the appropriate pins prior to being activated and prior to any related interrupt(s) being enabled. Activity of any enabled peripheral function that is not mapped to a related pin should be considered undefined.

Most pins can also be configured as open-drain outputs or to have a pull-up, pull-down, or no resistor enabled.

7.9 General purpose DMA controller

The GPDMA is an AMBA AHB compliant peripheral allowing selected LPC1759/58/56/54/52/51 peripherals to have DMA support.

The GPDMA enables peripheral-to-memory, memory-to-peripheral, peripheral-to-peripheral, and memory-to-memory transactions. The source and destination areas can each be either a memory region or a peripheral, and can be accessed through the AHB master. The GPDMA controller allows data transfers between the USB and Ethernet (LPC1758 only) controllers and the various on-chip SRAM areas. The supported APB peripherals are SSP0/1, all UARTs, the I²S-bus interface, the ADC, and the DAC. Two match signals for each timer can be used to trigger DMA transfers.

Remark: Note that the DAC is not available on the LPC1752/51, and the I²S-bus interface is not available on the LPC1754/52/51.

LPC1759/58/56/54/52/51 DRAKE DRAKE

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7.9.1 Features

- Eight DMA channels. Each channel can support an unidirectional transfer.
- 16 DMA request lines.
- Single DMA and burst DMA request signals. Each peripheral connected to the DMA Controller can assert either a burst DMA request or a single DMA request. The DMA burst size is set by programming the DMA Controller.
- Memory-to-memory, memory-to-peripheral, peripheral-to-memory, and peripheral-to-peripheral transfers are supported.
- Scatter or gather DMA is supported through the use of linked lists. This means that the source and destination areas do not have to occupy contiguous areas of memory.
- Hardware DMA channel priority.
- AHB slave DMA programming interface. The DMA Controller is programmed by writing to the DMA control registers over the AHB slave interface.
- One AHB bus master for transferring data. The interface transfers data when a DMA request goes active.
- 32-bit AHB master bus width.
- Incrementing or non-incrementing addressing for source and destination.
- Programmable DMA burst size. The DMA burst size can be programmed to more efficiently transfer data.
- Internal four-word FIFO per channel.
- Supports 8, 16, and 32-bit wide transactions.
- Big-endian and little-endian support. The DMA Controller defaults to little-endian mode on reset.
- An interrupt to the processor can be generated on a DMA completion or when a DMA error has occurred.
- Raw interrupt status. The DMA error and DMA count raw interrupt status can be read prior to masking.

7.10 Fast general purpose parallel I/O

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back as well as the current state of the port pins.

LPC1759/58/56/54/52/51 use accelerated GPIO functions:

- GPIO registers are accessed through the AHB multilayer bus so that the fastest possible I/O timing can be achieved.
- Mask registers allow treating sets of port bits as a group, leaving other bits unchanged.
- All GPIO registers are byte and half-word addressable.
- Entire port value can be written in one instruction.
- Support for Cortex-M3 bit banding.
- Support for use with the GPDMA controller.

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Additionally, any pin on PORT0 and PORT2 (total of 42 pins) providing a digital function can be programmed to generate an interrupt on a rising edge, a falling edge, or both. The edge detection is asynchronous, so it may operate when clocks are not present such as during Power-down mode. Each enabled interrupt can be used to wake up the chip from Power-down mode.

7.10.1 Features

- Bit level set and clear registers allow a single instruction to set or clear any number of bits in one port.
- Direction control of individual bits.
- All I/O default to inputs after reset.
- Pull-up/pull-down resistor configuration and open-drain configuration can be programmed through the pin connect block for each GPIO pin.

7.11 Ethernet (LPC1758 only)

The Ethernet block contains a full featured 10 Mbit/s or 100 Mbit/s Ethernet MAC designed to provide optimized performance through the use of DMA hardware acceleration. Features include a generous suite of control registers, half or full duplex operation, flow control, control frames, hardware acceleration for transmit retry, receive packet filtering and wake-up on LAN activity. Automatic frame transmission and reception with scatter-gather DMA off-loads many operations from the CPU.

The Ethernet block and the CPU share the ARM Cortex-M3 D-code and system bus through the AHB-multilayer matrix to access the various on-chip SRAM blocks for Ethernet data, control, and status information.

The Ethernet block interfaces between an off-chip Ethernet PHY using the Reduced MII (RMII) protocol and the on-chip Media Independent Interface Management (MIIM) serial bus.

The Ethernet block supports bus clock rates of up to 100 MHz.

7.11.1 Features

- Ethernet standards support:
 - Supports 10 Mbit/s or 100 Mbit/s PHY devices including 10 Base-T, 100 Base-TX, 100 Base-FX, and 100 Base-T4.
 - Fully compliant with IEEE standard 802.3.
 - Fully compliant with 802.3x full duplex flow control and half duplex back pressure.
 - Flexible transmit and receive frame options.
 - Virtual Local Area Network (VLAN) frame support.
- Memory management:
 - Independent transmit and receive buffers memory mapped to shared SRAM.
 - DMA managers with scatter/gather DMA and arrays of frame descriptors.
 - Memory traffic optimized by buffering and pre-fetching.
- Enhanced Ethernet features:

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- Receive filtering.
- Multicast and broadcast frame support for both transmit and receive.
- SRAFT DRAFT DRAFT - Optional automatic Frame Check Sequence (FCS) insertion with Cyclic Redundancy Check (CRC) for transmit.
- Selectable automatic transmit frame padding.
- Over-length frame support for both transmit and receive allows any length frames.
- Promiscuous receive mode.
- Automatic collision back-off and frame retransmission.
- Includes power management by clock switching.
- Wake-on-LAN power management support allows system wake-up: using the receive filters or a magic frame detection filter.
- Physical interface:
 - Attachment of external PHY chip through standard RMII interface.
 - PHY register access is available via the MIIM interface.

7.12 USB interface

The Universal Serial Bus (USB) is a 4-wire bus that supports communication between a host and one or more (up to 127) peripherals. The host controller allocates the USB bandwidth to attached devices through a token-based protocol. The bus supports hot plugging and dynamic configuration of the devices. All transactions are initiated by the host controller.

The LPC1759/58/56/54 USB interface includes a device, Host, and OTG controller with on-chip PHY for device and Host functions. The OTG switching protocol is supported through the use of an external controller. Details on typical USB interfacing solutions can be found in Section 14.1. The LPC1752/51 include a USB device controller only.

7.12.1 USB device controller

The device controller enables 12 Mbit/s data exchange with a USB Host controller. It consists of a register interface, serial interface engine, endpoint buffer memory, and a DMA controller. The serial interface engine decodes the USB data stream and writes data to the appropriate endpoint buffer. The status of a completed USB transfer or error condition is indicated via status registers. An interrupt is also generated if enabled. When enabled, the DMA controller transfers data between the endpoint buffer and the on-chip SRAM.

7.12.1.1 Features

- Fully compliant with USB 2.0 specification (full speed).
- Supports 32 physical (16 logical) endpoints with a 4 kB endpoint buffer RAM.
- Supports Control, Bulk, Interrupt and Isochronous endpoints.
- Scalable realization of endpoints at run time.
- Endpoint Maximum packet size selection (up to USB maximum specification) by software at run time.
- Supports SoftConnect and GoodLink features.

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- While USB is in the Suspend mode, the LPC1759/58/56/54/52/51 can enter one of the reduced power modes and wake up on USB activity. RAETU ADRI
- Supports DMA transfers with all on-chip SRAM blocks on all non-control endpoints.
- Allows dynamic switching between CPU-controlled slave and DMA modes.
- Double buffer implementation for Bulk and Isochronous endpoints.

7.12.2 USB host controller (LPC1759/58/56/54 only).

The host controller enables full- and low-speed data exchange with USB devices attached to the bus. It consists of a register interface, a serial interface engine, and a DMA controller. The register interface complies with the Open Host Controller Interface (OHCI) specification.

7.12.2.1 Features

- OHCI compliant.
- One downstream port.
- Supports port power switching.

7.12.3 USB OTG controller (LPC1759/58/56/54 only).

USB OTG is a supplement to the USB 2.0 specification that augments the capability of existing mobile devices and USB peripherals by adding host functionality for connection to USB peripherals.

The OTG Controller integrates the host controller, device controller, and a master-only I²C-bus interface to implement OTG dual-role device functionality. The dedicated I²C-bus interface controls an external OTG transceiver.

7.12.3.1 Features

- Fully compliant with On-The-Go supplement to the USB 2.0 Specification, Revision 1.0a.
- Hardware support for Host Negotiation Protocol (HNP).
- Includes a programmable timer required for HNP and Session Request Protocol (SRP).
- Supports any OTG transceiver compliant with the OTG Transceiver Specification (CEA-2011), Rev. 1.0.

7.13 CAN controller and acceptance filters

The Controller Area Network (CAN) is a serial communications protocol which efficiently supports distributed real-time control with a very high level of security. Its domain of application ranges from high-speed networks to low cost multiplex wiring.

The CAN block is intended to support multiple CAN buses simultaneously, allowing the device to be used as a gateway, switch, or router among a number of CAN buses in industrial or automotive applications.

Remark: LPC1754/52/51 have only one CAN bus.

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7.13.1 Features

- One or two CAN controllers and buses.
- Data rates to 1 Mbit/s on each bus.
- 32-bit register and RAM access.
- Compatible with CAN specification 2.0B, ISO 11898-1.
- Global Acceptance Filter recognizes standard (11-bit) and extended-frame (29-bit) receive identifiers for all CAN buses.
- Acceptance Filter can provide FullCAN-style automatic reception for selected Standard Identifiers.
- FullCAN messages can generate interrupts.

7.14 12-bit ADC

The LPC1759/58/56/54/52/51 contain one ADC. It is a single 12-bit successive approximation ADC with six channels and DMA support.

7.14.1 Features

- 12-bit successive approximation ADC.
- Input multiplexing among 6 pins.
- Power-down mode.
- Measurement range VREFN to VREFP.
- 12-bit conversion rate: 200 kHz.
- Individual channels can be selected for conversion.
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition of input pin or Timer Match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.
- DMA support.

7.15 10-bit DAC (LPC1759/58/56/54 only)

The DAC allows to generate a variable analog output. The maximum output value of the DAC is VREFP.

7.15.1 Features

- 10-bit DAC
- Resistor string architecture
- Buffered output
- Power-down mode
- Selectable output drive
- Dedicated conversion timer
- DMA support

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7.16 UARTs

ORS: DRAFT DRA The LPC1759/58/56/54/52/51 each contain four UARTs. In addition to standard transmit and receive data lines, UART1 also provides a full modem control handshake interface and support for RS-485/9-bit mode allowing both software address detection and automatic address detection using 9-bit mode.

The UARTs include a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

7.16.1 Features

- Maximum UART data bit rate of 6.25 MBit/s.
- 16 B Receive and Transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- · Fractional divider for baud rate control, auto baud capabilities and FIFO control mechanism that enables software flow control implementation.
- UART1 equipped with standard modem interface signals. This module also provides full support for hardware flow control (auto-CTS/RTS).
- Support for RS-485/9-bit/EIA-485 mode (UART1).
- UART3 includes an IrDA mode to support infrared communication.
- All UARTs have DMA support.

7.17 SPI serial I/O controller

The LPC1759/58/56/54/52/51 contain one SPI controller. SPI is a full duplex serial interface designed to handle multiple masters and slaves connected to a given bus. Only a single master and a single slave can communicate on the interface during a given data transfer. During a data transfer the master always sends 8 bits to 16 bits of data to the slave, and the slave always sends 8 bits to 16 bits of data to the master.

7.17.1 Features

- Maximum SPI data bit rate of 12.5 Mbit/s
- Compliant with SPI specification
- Synchronous, serial, full duplex communication
- Combined SPI master and slave
- Maximum data bit rate of one eighth of the input clock rate
- 8 bits to 16 bits per transfer

7.18 SSP serial I/O controller

The LPC1759/58/56/54/52/51 contain two SSP controllers. The SSP controller is capable of operation on a SPI, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the

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Dr. DRAFT D TRAFT DRI bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bits to 16 bits of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.18.1 Features

- Maximum SSP speed of 50 Mbit/s (master) or 8 Mbit/s (slave)
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses
- Synchronous serial communication
- Master or slave operation
- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame
- DMA transfers supported by GPDMA

7.19 I²C-bus serial I/O controllers

The LPC1759/58/56/54/52/51 each contain two I²C-bus controllers.

The I²C-bus is bidirectional for inter-IC control using only two wires: a Serial Clock Line (SCL) and a Serial Data Line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C is a multi-master bus and can be controlled by more than one bus master connected to it.

7.19.1 Features

- I²C1 and I²C2 use standard I/O pins with bit rates of up to 400 kbit/s (Fast I²C-bus).
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.
- Both I²C-bus controllers support multiple address recognition and a bus monitor mode.

7.20 I²S-bus serial I/O controllers (LPC1759/58/56 only)

The I²S-bus provides a standard communication interface for digital audio applications.

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The l^2S -bus specification defines a 3-wire serial bus using one data line, one clock line, and one word select signal. The basic l^2S connection has one master, which is always the master, and one slave. The l^2S -bus interface provides a separate transmit and receive channel, each of which can operate as either a master or a slave.

7.20.1 Features

- The interface has separate input/output channels each of which can operate in master or slave mode.
- Capable of handling 8-bit, 16-bit, and 32-bit word sizes.
- Mono and stereo audio data supported.
- The sampling frequency can range from 16 kHz to 96 kHz (16, 22.05, 32, 44.1, 48, 96) kHz.
- Support for an audio master clock.
- Configurable word select period in master mode (separately for I²S input and output).
- Two 8-word FIFO data buffers are provided, one for transmit and one for receive.
- Generates interrupt requests when buffer levels cross a programmable boundary.
- Two DMA requests, controlled by programmable buffer levels. These are connected to the GPDMA block.
- Controls include reset, stop and mute options separately for I²S input and I²S output.

7.21 General purpose 32-bit timers/external event counters

The LPC1759/58/56/54/52/51 include four 32-bit timer/counters. The timer/counter is designed to count cycles of the system derived clock or an externally-supplied clock. It can optionally generate interrupts, generate timed DMA requests, or perform other actions at specified timer values, based on four match registers. Each timer/counter also includes two capture inputs to trap the timer value when an input signal transitions, optionally generating an interrupt.

7.21.1 Features

- A 32-bit timer/counter with a programmable 32-bit prescaler.
- Counter or timer operation.
- Two 32-bit capture channels per timer, that can take a snapshot of the timer value when an input signal transitions. A capture event may also generate an interrupt.
- Four 32-bit match registers that allow:
 - Continuous operation with optional interrupt generation on match.
 - Stop timer on match with optional interrupt generation.
 - Reset timer on match with optional interrupt generation.
- Up to four external outputs corresponding to match registers, with the following capabilities:
 - Set LOW on match.
 - Set HIGH on match.
 - Toggle on match.
 - Do nothing on match.

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Up to two match registers can be used to generate timed DMA requests.

7.22 Pulse width modulator

DRAK TORAK The PWM is based on the standard Timer block and inherits all of its features, although only the PWM function is pinned out on the LPC1759/58/56/54/52/51. The Timer is designed to count cycles of the system derived clock and optionally switch pins, generate interrupts or perform other actions when specified timer values occur, based on seven match registers. The PWM function is in addition to these features, and is based on match register events.

The ability to separately control rising and falling edge locations allows the PWM to be used for more applications. For instance, multi-phase motor control typically requires three non-overlapping PWM outputs with individual control of all three pulse widths and positions.

Two match registers can be used to provide a single edge controlled PWM output. One match register (PWMMR0) controls the PWM cycle rate, by resetting the count upon match. The other match register controls the PWM edge position. Additional single edge controlled PWM outputs require only one match register each, since the repetition rate is the same for all PWM outputs. Multiple single edge controlled PWM outputs will all have a rising edge at the beginning of each PWM cycle, when an PWMMR0 match occurs.

Three match registers can be used to provide a PWM output with both edges controlled. Again, the PWMMR0 match register controls the PWM cycle rate. The other match registers control the two PWM edge positions. Additional double edge controlled PWM outputs require only two match registers each, since the repetition rate is the same for all PWM outputs.

With double edge controlled PWM outputs, specific match registers control the rising and falling edge of the output. This allows both positive going PWM pulses (when the rising edge occurs prior to the falling edge), and negative going PWM pulses (when the falling edge occurs prior to the rising edge).

7.22.1 Features

- LPC1759/58/56/54/52/51 has one PWM block with Counter or Timer operation (may use the peripheral clock or one of the capture inputs as the clock source).
- Seven match registers allow up to 6 single edge controlled or 3 double edge controlled PWM outputs, or a mix of both types. The match registers also allow:
 - Continuous operation with optional interrupt generation on match.
 - Stop timer on match with optional interrupt generation.
 - Reset timer on match with optional interrupt generation.
- Supports single edge controlled and/or double edge controlled PWM outputs. Single edge controlled PWM outputs all go high at the beginning of each cycle unless the output is a constant low. Double edge controlled PWM outputs can have either edge occur at any position within a cycle. This allows for both positive going and negative going pulses.
- Pulse period and width can be any number of timer counts. This allows complete flexibility in the trade-off between resolution and repetition rate. All PWM outputs will occur at the same repetition rate.

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- Double edge controlled PWM outputs can be programmed to be either positive going or negative going pulses.
- Match register updates are synchronized with pulse outputs to prevent generation of erroneous pulses. Software must 'release' new match values before they can become effective.
- May be used as a standard 32-bit timer/counter with a programmable 32-bit prescaler if the PWM mode is not enabled.

7.23 Motor control PWM

The motor control PWM is a specialized PWM supporting 3-phase motors and other combinations. Feedback inputs are provided to automatically sense rotor position and use that information to ramp speed up or down. At the same time, the motor control PWM is highly configurable for other generalized timing, counting, capture, and compare applications.

7.24 Quadrature Encoder Interface (QEI)

A quadrature encoder, also known as a 2-channel incremental encoder, converts angular displacement into two pulse signals. By monitoring both the number of pulses and the relative phase of the two signals, the user can track the position, direction of rotation, and velocity. In addition, a third channel, or index signal, can be used to reset the position counter. The quadrature encoder interface decodes the digital pulses from a quadrature encoder wheel to integrate position over time and determine direction of rotation. In addition, the QEI can capture the velocity of the encoder wheel.

7.24.1 Features

- Tracks encoder position.
- Increments/decrements depending on direction.
- Programmable for 2x or 4x position counting.
- Velocity capture using built-in timer.
- Velocity compare function with "less than" interrupt.
- Uses 32-bit registers for position and velocity.
- Three position compare registers with interrupts.
- Index counter for revolution counting.
- Index compare register with interrupts.
- Can combine index and position interrupts to produce an interrupt for whole and partial revolution displacement.
- Digital filter with programmable delays for encoder input signals.
- Can accept decoded signal inputs (clk and direction).
- Connected to APB.

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7.25 Repetitive Interrupt (RI) timer

The repetitive interrupt timer provides a free-running 32-bit counter which is compared to a selectable value, generating an interrupt when a match occurs. Any bits of the timer/compare can be masked such that they do not contribute to the match detection. The repetitive interrupt timer can be used to create an interrupt that repeats at predetermined intervals.

7.25.1 Features

- 32-bit counter running from PCLK. Counter can be free-running or be reset by a generated interrupt.
- 32-bit compare value.
- 32-bit compare mask. An interrupt is generated when the counter value equals the compare value, after masking. This allows for combinations not possible with a simple compare.

7.26 ARM Cortex-M3 system tick timer

The ARM Cortex-M3 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a 10 ms interval. In the LPC1759/58/56/54/52/51, this timer can be clocked from the internal AHB clock or from a device pin.

7.27 Watchdog timer

The purpose of the watchdog is to reset the microcontroller within a reasonable amount of time if it enters an erroneous state. When enabled, the watchdog will generate a system reset if the user program fails to 'feed' (or reload) the watchdog within a predetermined amount of time.

7.27.1 Features

- Internally resets chip if not periodically reloaded.
- Debug mode.
- Enabled by software but requires a hardware reset or a watchdog reset/interrupt to be disabled.
- Incorrect/Incomplete feed sequence causes reset/interrupt if enabled.
- Flag to indicate watchdog reset.
- Programmable 32-bit timer with internal prescaler.
- Selectable time period from $(T_{cy(WDCLK)} \times 256 \times 4)$ to $(T_{cy(WDCLK)} \times 2^{32} \times 4)$ in multiples of $T_{cy(WDCLK)} \times 4$.
- The Watchdog Clock (WDCLK) source can be selected from the Internal RC (IRC) oscillator, the RTC oscillator, or the APB peripheral clock. This gives a wide range of potential timing choices of Watchdog operation under different power reduction conditions. It also provides the ability to run the WDT from an entirely internal source that is not dependent on an external crystal and its associated components and wiring for increased reliability.
- Includes lock/safe feature.

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7.28 RTC and backup registers

The RTC is a set of counters for measuring time when system power is on, and optionally when it is off. The RTC on the LPC1759/58/56/54/52/51 is designed to have extremely low power consumption, i.e. less than 1 μ A. The RTC will typically run from the main chip power supply, conserving battery power while the rest of the device is powered up. When operating from a battery, the RTC will continue working down to 2.1 V. Battery power can be provided from a standard 3 V Lithium button cell.

An ultra-low power 32 kHz oscillator will provide a 1 Hz clock to the time counting portion of the RTC, moving most of the power consumption out of the time counting function.

The RTC includes a calibration mechanism to allow fine-tuning the count rate in a way that will provide less than 1 second per day error when operated at a constant voltage and temperature.

The RTC contains a small set of backup registers (20 bytes) for holding data while the main part of the LPC1759/58/56/54/52/51 is powered off.

The RTC includes an alarm function that can wake up the LPC1759/58/56/54/52/51 from all reduced power modes with a time resolution of 1 s.

7.28.1 Features

- Measures the passage of time to maintain a calendar and clock.
- Ultra low power design to support battery powered systems.
- Provides Seconds, Minutes, Hours, Day of Month, Month, Year, Day of Week, and Day of Year.
- Dedicated power supply pin can be connected to a battery or to the main 3.3 V.
- Periodic interrupts can be generated from increments of any field of the time registers.
- Backup registers (20 bytes) powered by VBAT.
- RTC power supply is isolated from the rest of the chip.

7.29 Clocking and power control

7.29.1 Crystal oscillators

The LPC1759/58/56/54/52/51 include three independent oscillators. These are the main oscillator, the IRC oscillator, and the RTC oscillator. Each oscillator can be used for more than one purpose as required in a particular application. Any of the three clock sources can be chosen by software to drive the main PLL and ultimately the CPU.

Following reset, the LPC1759/58/56/54/52/51 will operate from the Internal RC oscillator until switched by software. This allows systems to operate without any external crystal and the bootloader code to operate at a known frequency.

See Figure 4 for an overview of the LPC1759/58/56/54/52/51 clock generation.

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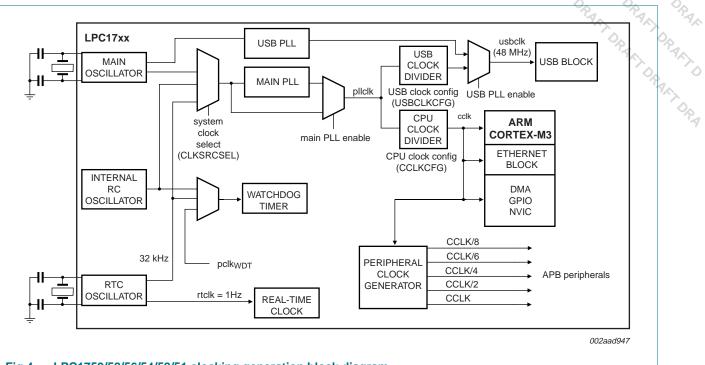


Fig 4. LPC1759/58/56/54/52/51 clocking generation block diagram

7.29.1.1 Internal RC oscillator

The IRC may be used as the clock source for the WDT, and/or as the clock that drives the PLL and subsequently the CPU. The nominal IRC frequency is 4 MHz. The IRC is trimmed to 1 % accuracy over the entire voltage and temperature range.

Upon power-up or any chip reset, the LPC1759/58/56/54/52/51 use the IRC as the clock source. Software may later switch to one of the other available clock sources.

7.29.1.2 Main oscillator

The main oscillator can be used as the clock source for the CPU, with or without using the PLL. The main oscillator also provides the clock source for the dedicated USB PLL.

The main oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the main PLL. The clock selected as the PLL input is PLLCLKIN. The ARM processor clock frequency is referred to as CCLK elsewhere in this document. The frequencies of PLLCLKIN and CCLK are the same value unless the PLL is active and connected. The clock frequency for each peripheral can be selected individually and is referred to as PCLK. Refer to Section 7.29.2 for additional information.

7.29.1.3 RTC oscillator

The RTC oscillator can be used as the clock source for the RTC block, the main PLL, and/or the CPU.

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7.29.2 Main PLL (PLL0)

The PLL0 accepts an input clock frequency in the range of 32 kHz to 25 MHz. The input frequency is multiplied up to a high frequency, then divided down to provide the actual clock used by the CPU and/or the USB block.

The PLL0 input, in the range of 32 kHz to 25 MHz, may initially be divided down by a value 'N', which may be in the range of 1 to 256. This input division provides a wide range of output frequencies from the same input frequency.

Following the PLL0 input divider is the PLL0 multiplier. This can multiply the input divider output through the use of a Current Controlled Oscillator (CCO) by a value 'M', in the range of 1 through 32768. The resulting frequency must be in the range of 275 MHz to 550 MHz. The multiplier works by dividing the CCO output by the value of M, then using a phase-frequency detector to compare the divided CCO output to the multiplier input. The error value is used to adjust the CCO frequency.

The PLL0 is turned off and bypassed following a chip Reset and by entering Power-down mode. PLL0 is enabled by software only. The program must configure and activate the PLL0, wait for the PLL0 to lock, and then connect to the PLL0 as a clock source.

7.29.3 USB PLL (PLL1)

The LPC1759/58/56/54/52/51 contain a second, dedicated USB PLL1 to provide clocking for the USB interface.

The PLL1 receives its clock input from the main oscillator only and provides a fixed 48 MHz clock to the USB block only. The PLL1 is disabled and powered off on reset. If the PLL1 is left disabled, the USB clock will be supplied by the 48 MHz clock from the main PLL0.

The PLL1 accepts an input clock frequency in the range of 10 MHz to 25 MHz only. The input frequency is multiplied up the range of 48 MHz for the USB clock using a Current Controlled Oscillators (CCO). It is insured that the PLL1 output has a 50% duty cycle.

7.29.4 Wake-up timer

The LPC1759/58/56/54/52/51 begin operation at power-up and when awakened from Power-down mode by using the 4 MHz IRC oscillator as the clock source. This allows chip operation to resume quickly. If the main oscillator or the PLL is needed by the application, software will need to enable these features and wait for them to stabilize before they are used as a clock source.

When the main oscillator is initially activated, the wake-up timer allows software to ensure that the main oscillator is fully functional before the processor uses it as a clock source and starts to execute instructions. This is important at power on, all types of Reset, and whenever any of the aforementioned functions are turned off for any reason. Since the oscillator and other functions are turned off during Power-down mode, any wake-up of the processor from Power-down mode makes use of the wake-up Timer.

The Wake-up Timer monitors the crystal oscillator to check whether it is safe to begin code execution. When power is applied to the chip, or when some event caused the chip to exit Power-down mode, some time is required for the oscillator to produce a signal of sufficient amplitude to drive the clock logic. The amount of time depends on many factors, including the rate of $V_{DD(3V3)}$ ramp (in the case of power on), the type of crystal and its

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electrical characteristics (if a quartz crystal is used), as well as any other external circuitry (e.g., capacitors), and the characteristics of the oscillator itself under the existing ambient conditions.

7.29.5 Power control

The LPC1759/58/56/54/52/51 support a variety of power control features. There are four special modes of processor power reduction: Sleep mode, Deep-sleep mode, Power-down mode, and Deep power-down mode. The CPU clock rate may also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This allows a trade-off of power versus processing speed based on application requirements. In addition, Peripheral Power Control allows shutting down the clocks to individual on-chip peripherals, allowing fine tuning of power consumption by eliminating all dynamic power use in any peripherals that are not required for the application. Each of the peripherals has its own clock divider which provides even better power control.

Integrated PMU (Power Management Unit) automatically adjust internal regulators to minimize power consumption during Sleep, Deep sleep, Power-down, and Deep power-down modes.

The LPC1759/58/56/54/52/51 also implement a separate power domain to allow turning off power to the bulk of the device while maintaining operation of the RTC and a small set of registers for storing data during any of the power-down modes.

7.29.5.1 Sleep mode

When Sleep mode is entered, the clock to the core is stopped. Resumption from the Sleep mode does not need any special sequence but re-enabling the clock to the ARM core.

In Sleep mode, execution of instructions is suspended until either a Reset or interrupt occurs. Peripheral functions continue operation during Sleep mode and may generate interrupts to cause the processor to resume execution. Sleep mode eliminates dynamic power used by the processor itself, memory systems and related controllers, and internal buses.

7.29.5.2 Deep-sleep mode

In Deep-sleep mode, the oscillator is shut down and the chip receives no internal clocks. The processor state and registers, peripheral registers, and internal SRAM values are preserved throughout Deep-sleep mode and the logic levels of chip pins remain static. The output of the IRC is disabled but the IRC is not powered down for a fast wake-up later. The RTC oscillator is not stopped because the RTC interrupts may be used as the wake-up source. The PLL is automatically turned off and disconnected. The CCLK and USB clock dividers automatically get reset to zero.

The Deep-sleep mode can be terminated and normal operation resumed by either a Reset or certain specific interrupts that are able to function without clocks. Since all dynamic operation of the chip is suspended, Deep-sleep mode reduces chip power consumption to a very low value. Power to the flash memory is left on in Deep-sleep mode, allowing a very quick wake-up.

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On wake-up from Deep-sleep mode, the code execution and peripherals activities will resume after 4 cycles expire if the IRC was used before entering Deep-sleep mode. If the PACT DR expire. PLL and clock dividers need to be reconfigured accordingly.

7.29.5.3 Power-down mode

Power-down mode does everything that Deep-sleep mode does, but also turns off the power to the IRC oscillator and the flash memory. This saves more power but requires waiting for resumption of flash operation before execution of code or data access in the flash memory can be accomplished.

On the wake-up of Power-down mode, if the IRC was used before entering Power-down mode, it will take IRC 60 µs to start-up. After this 4 IRC cycles will expire before the code execution can then be resumed if the code was running from SRAM. In the meantime, the flash wake-up timer then counts 4 MHz IRC clock cycles to make the 100 µs flash start-up time. When it times out, access to the flash will be allowed. Users need to reconfigure the PLL and clock dividers accordingly.

7.29.5.4 Deep power-down mode

The Deep power-down mode can only be entered from the RTC block. In Deep power-down mode, power is shut off to the entire chip with the exception of the RTC module and the RESET pin.

The LPC1759/58/56/54/52/51 can wake up from Deep power-down mode via the RESET pin or an alarm match event of the RTC.

7.29.5.5 Wakeup interrupt controller

The Wakeup Interrupt Controller (WIC) allows the CPU to automatically wake up from any enabled priority interrupt that can occur while the clocks are stopped in Deep sleep, Power-down, and Deep power-down modes.

The Wake-up controller (WIC) works in connection with the Nested Vectored Interrupt Controller (NVIC). When the CPU enters Deep sleep, Power-down, or Deep power-down mode, the NVIC sends a mask of the current interrupt situation to the WIC. This mask includes all of the interrupts that are both enabled and of sufficient priority to be serviced immediately. With this information, the WIC simply notices when one of the interrupts has occurred and then it wakes up the CPU.

The Wake-up controller (WIC) eliminates the need to periodically wake up the CPU and poll the interrupts resulting in additional power savings.

7.29.6 Peripheral power control

A Power Control for Peripherals feature allows individual peripherals to be turned off if they are not needed in the application, resulting in additional power savings.

7.29.7 Power domains

The LPC1759/58/56/54/52/51 provide two independent power domains that allow the bulk of the device to have power removed while maintaining operation of the RTC and the backup Registers.

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On the LPC1759/58/56/54/52/51, I/O pads are powered by the 3.3 V ($V_{DD(3V3)}$) pins, while the $V_{DD(REG)(3V3)}$ pin powers the on-chip voltage regulator which in turn provides power to the CPU and most of the peripherals.

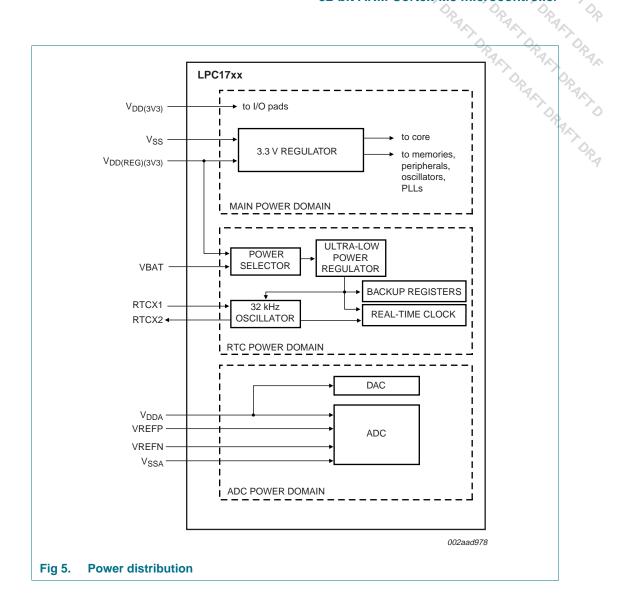
Depending on the LPC1759/58/56/54/52/51 application, a design can use two power options to manage power consumption.

The first option assumes that power consumption is not a concern and the design ties the $V_{DD(3V3)}$ and $V_{DD(REG)(3V3)}$ pins together. This approach requires only one 3.3 V power supply for both pads, the CPU, and peripherals. While this solution is simple, it does not support powering down the I/O pad ring "on the fly" while keeping the CPU and peripherals alive.

The second option uses two power supplies; a 3.3 V supply for the I/O pads ($V_{DD(3V3)}$) and a dedicated 3.3 V supply for the CPU ($V_{DD(REG)(3V3)}$). Having the on-chip voltage regulator powered independently from the I/O pad ring enables shutting down of the I/O pad power supply "on the fly", while the CPU and peripherals stay active.

The VBAT pin supplies power only to the RTC domain. The RTC requires a minimum of power to operate, which can be supplied by an external battery. The device core power $(V_{DD(REG)(3V3)})$ is used to operate the RTC whenever $V_{DD(REG)(3V3)}$ is present. Therefore, there is no power drain from the RTC battery when $V_{DD(REG)(3V3)}$ is available.

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7.30 System control

7.30.1 Reset

Reset has four sources on the LPC1759/58/56/54/52/51: the RESET pin, the Watchdog reset, power-on reset (POR), and the BrownOut Detection (BOD) circuit. The RESET pin is a Schmitt trigger input pin. Assertion of chip Reset by any source, once the operating voltage attains a usable level, starts the Wake-up timer (see description in <u>Section 7.29.4</u>), causing reset to remain asserted until the external Reset is de-asserted, the oscillator is running, a fixed number of clocks have passed, and the flash controller has completed its initialization.

When the internal Reset is removed, the processor begins executing at address 0, which is initially the Reset vector mapped from the Boot Block. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

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7.30.2 Brownout detection

The LPC1759/58/56/54/52/51 include 2-stage monitoring of the voltage on the $V_{DD(REG)(3V3)}$ pins. If this voltage falls below 2.95 V, the BOD asserts an interrupt signal to the Vectored Interrupt Controller. This signal can be enabled for interrupt in the Interrupt Enable Register in the NVIC in order to cause a CPU interrupt; if not, software can monitor the signal by reading a dedicated status register.

The second stage of low-voltage detection asserts reset to inactivate the LPC1759/58/56/54/52/51 when the voltage on the $V_{DD(REG)(3V3)}$ pins falls below 2.65 V. This reset prevents alteration of the flash as operation of the various elements of the chip would otherwise become unreliable due to low voltage. The BOD circuit maintains this reset down below 1 V, at which point the power-on reset circuitry maintains the overall reset.

Both the 2.95 V and 2.65 V thresholds include some hysteresis. In normal operation, this hysteresis allows the 2.95 V detection to reliably interrupt, or a regularly executed event loop to sense the condition.

7.30.3 Code security (Code Read Protection - CRP)

This feature of the LPC1759/58/56/54/52/51 allows user to enable different levels of security in the system so that access to the on-chip flash and use of the JTAG and ISP can be restricted. When needed, CRP is invoked by programming a specific pattern into a dedicated flash location. IAP commands are not affected by the CRP.

There are three levels of the Code Read Protection.

CRP1 disables access to chip via the JTAG and allows partial flash update (excluding flash sector 0) using a limited set of the ISP commands. This mode is useful when CRP is required and flash field updates are needed but all sectors can not be erased.

CRP2 disables access to chip via the JTAG and only allows full flash erase and update using a reduced set of the ISP commands.

Running an application with level CRP3 selected fully disables any access to chip via the JTAG pins and the ISP. This mode effectively disables ISP override using P2[10] pin, too. It is up to the user's application to provide (if needed) flash update mechanism using IAP calls or call reinvoke ISP command to enable flash update via UART0.

CAUTION



If level three Code Read Protection (CRP3) is selected, no future factory testing can be performed on the device.

7.30.4 APB interface

The APB peripherals are split into two separate APB buses in order to distribute the bus bandwidth and thereby reducing stalls caused by contention between the CPU and the GPDMA controller.

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7.30.5 AHB multilayer matrix

The LPC1759/58/56/54/52/51 use an AHB multilayer matrix. This matrix connects the instruction (I-code) and data (D-code) CPU buses of the ARM Cortex-M3 to the flash memory, the main (32 kB) static RAM, and the Boot ROM. The GPDMA can also access all of these memories. The peripheral DMA controllers, Ethernet (LPC1758 only) and USB, can access all SRAM blocks. Additionally, the matrix connects the CPU system bus and all of the DMA controllers to the various peripheral functions.

7.30.6 External interrupt inputs

The LPC1759/58/56/54/52/51 include up to 30 edge sensitive interrupt inputs combined with one level sensitive external interrupt input as selectable pin function. The external interrupt input can optionally be used to wake up the processor from Power-down mode.

7.30.7 Memory mapping control

The Cortex-M3 incorporates a mechanism that allows remapping the interrupt vector table to alternate locations in the memory map. This is controlled via the Vector Table Offset Register contained in the NVIC.

The vector table may be located anywhere within the bottom 1 GB of Cortex-M3 address space. The vector table must be located on a 128 word (512 byte) boundary because the NVIC on the LPC1759/58/56/54/52/51 is configured for 128 total interrupts.

7.31 Emulation and debugging

Debug and trace functions are integrated into the ARM Cortex-M3. Serial wire debug and trace functions are supported in addition to a standard JTAG debug and parallel trace functions. The ARM Cortex-M3 is configured to support up to eight breakpoints and four watch points.

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Limiting values 8.

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DD(3V3)}	supply voltage (3.3 V)	core and external rail	2.4	3.6	Unit V
V _{DD(REG)(3V3)}	regulator supply voltage (3.3 V)		2.4	3.6	V
V _{DDA}	analog 3.3 V pad supply voltage		-0.5	+4.6	V
V _{i(VBAT)}	input voltage on pin VBAT	for the RTC	-0.5	+4.6	V
V _{i(VREFP)}	input voltage on pin VREFP		-0.5	+4.6	V
V _{IA}	analog input voltage	on ADC related pins	-0.5	+5.1	V
VI	input voltage	5 V tolerant I/O pins; only valid when the $V_{DD(3V3)}$ supply voltage is present	2 -0.5	+5.5	V
		other I/O pins	[2][3] _0.5	V _{DD(3V3)} + 0.5	V
I _{DD}	supply current	per supply pin	<u>[4]</u> _	100	mA
I _{SS}	ground current	per ground pin	<u>[4]</u> _	100	mA
l _{latch}	I/O latch-up current	–(0.5V _{DD(3V3)}) < V _I < (1.5V _{DD(3V3)}); T _i < 125 °C	-	100	mA
T _{stg}	storage temperature	,	<u>[5]</u> –65	+150	°C
P _{tot(pack)}	total power dissipation (per package)	based on package heat transfer, not device power consumption	-	1.5	W
V _{ESD}	electrostatic discharge voltage	human body model; all pins	<u>6</u> –4000	+4000	V

[1] The following applies to the limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Including voltage on outputs in 3-state mode.

[3] Not to exceed 4.6 V.

The peak current is limited to 25 times the corresponding maximum current. [4]

[5] Dependent on package type.

Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 k Ω series resistor. [6]

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9. **Thermal characteristics**

Thermal characteristics 9.1

The average chip junction temperature, T_J (°C), can be calculated using the following equation:

$$T_J = T_{amb} + (P_D \times R_{th(i-a)})$$

- T_{amb} = ambient temperature (°C),
- R_{th(j-a)} = the package junction-to-ambient thermal resistance (°C/W)
- P_D = sum of internal and I/O power dissipation

The internal power dissipation is the product of I_{DD} and V_{DD} . The I/O power dissipation of the I/O pins is often small and many times can be negligible. However it can be significant in some applications.

Thermal characteristics Table 5.

 V_{DD} = 2.4 V to 3.6 V; T_{amb} = -40 °C to +85 °C unless otherwise specified;

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T _{j(max)}	maximum junction temperature		-	-	125	°C

(1)

10. Static characteristics

Static characteristics Table 6.

 $T_{amb} = -40 \ ^{\circ}C$ to +85 $^{\circ}C$, unless otherwise specified.

				32-bit	ARM Cortex	M3 microc	controlle
10. Static	characteristics					OPA	Op A
	tic characteristics o +85 ℃, unless otherwise	specified.					DRAAN
Symbol	Parameter	Conditions		Min	Typ <mark>[1]</mark>	Max	Unit
Supply pins							
V _{DD(3V3)}	supply voltage (3.3 V)	core and external rail		2.4	3.3	3.6	V
V _{DD(REG)(3V3)}	regulator supply voltage (3.3 V)			2.4	3.3	3.6	V
V _{DDA}	analog 3.3 V pad supply voltage			2.7	3.3	3.6	V
V _{i(VBAT)}	input voltage on pin VBAT		[2]	2.1	3.3	3.6	V
V _{i(VREFP)}	input voltage on pin VREFP			2.7	3.3	V_{DDA}	V
I _{DD(REG)(3V3)}	regulator supply current	active mode; code					
	(3.3 V)	while(1){}					
		executed from flash; all peripherals disabled; PCLK = ^{CCLK} / ₈					
		CCLK = 12 MHz; PLL disabled	<u>[3]</u>	-	7	-	mA
		CCLK = 100 MHz; PLL enabled	<u>[3]</u>	-	42	-	mA
		CCLK = 120 MHz; PLL enabled	<u>[3][4]</u>	-	67	-	mA
		sleep mode	[3][5]	-	2	-	mA
		deep sleep mode	[3][6]	-	240	-	μA
		power-down mode	[3][6]	-	31	-	μA
		deep power-down mode; RTC not running	<u>[3]</u>	-	517	-	nA
I _{BAT}	battery supply current	deep power-down mode; RTC running					
		V _{DD(REG)(3V3)} present	[7]	-	134	-	nA
		$V_{DD(REG)(3V3)}$ not present	<u>[8]</u>	-	634	-	nA
I _{DD(IO)}	I/O supply current	deep sleep mode	<u>[9]</u>	-	40	-	nA
		power-down mode	<u>[9]</u>	-	40	-	nA
		deep power-down mode	<u>[9]</u>	-	10	-	nA
DD(ADC)	ADC supply current	deep sleep mode	[10]	-	38	-	nA
		power-down mode	[10]	-	38	-	nA
		deep power-down mode	<u>[10]</u>	-	24	-	nA
I _{I(ADC)}	ADC input current	on pin VREFP					
		deep sleep mode	[11]	-	100	-	nA
		power-down mode	[11]	-	100	-	nA
		deep power-down	[11]	-	100	-	nA



Table 6. Static characteristics ... continued

Standard port pins, RESET Image: Low level input current V = 0 V; on-chip pull-up resistor disabled - - 3 P Image: Imag	trolle	5/54/52 M3 microcor	M Cortex-	32-bit ARI				NXP Semic
Standard port pins, RESETILLLOW-level input currentV ₁ = 0 V; on-chip pull-up resistor disabled3pILHHIGH-level input currentV ₁ = V _{DD(3V3)} ; on-chip pull-down resistor 	0 _p	ORA ORA						
Standard port pins, RESET I_{IL} LOW-level input current $V_1 = 0$ (; on-chip pull-up resistor disabled3p I_{IH} HIGH-level input current $V_1 = V_{DD(3V3)}$; on-chip pull-down resistor disabled3p I_{OZ} OFF-state output current $V_0 = 0$ ($V_0 = V_{DD(3V3)}$; on-chip pull-up/down resistor disabled3p V_1 input voltagepin configured to provide a digital function[12](13] 0-5.0N V_0 output voltageoutput active0- $V_{DD(3V3)}$ N V_1 HIGH-level input voltage0.4N V_0 output voltage0.4N V_{0L} LOW-level input voltage0.4N V_{0L} LOW-level input voltage $I_{OL} = 4$ mA[15] $V_{DD(3V3)} = -$ -N V_{0L} UOW-level output voltage $I_{OL} = 0.4$ V15]-4r I_{0H} HIGH-level short-circuit output current $V_{OL} = 0.4$ V15]-4r I_{0H} UOW-level short-circuit output current $V_{OL} = V_{DD(3V3)}$ 15] I_{0H} UIGH-level short-circuit output current $V_{OL} = V_{DD(3V3)}$ 15]r I_{0H} UIGH-level short-circuit output current $V_{OL} = V_{DD(3V3)}$ 15]- </th <th>DRAS</th> <th>OPAN</th> <th></th> <th></th> <th></th> <th></th> <th></th> <th></th>	DRAS	OPAN						
Standard port pins, RESETIILLOW-level input currentV1 = V; on-chip pull-up resistor disabled3PII-HHIGH-level input currentV1 = VDD(3V3); on-chip pull-down resistor disabled3PIOzOFF-state output currentV0 = 0 V; V0 = VDD(3V3); on-chip pull-up/down resistor disabled3PV1input voltagepin configured to provide a digital functionIf 20-5.0NV0output voltageoutput active0-VD(3V3)NV1HIGH-level input voltage0.4NV0LOW-level input voltage0.4NV0HLOW-level output voltageIOH = -4 mAIf 9 UD(3V3) -NNV0LLOW-level output voltageIOL = 4 mAIf 9 UD(3V3)0.4NIOHHIGH-level output currentVOL = 0.4 VIf 9 UD(3V3)NIOHLOW-level output currentV0L = 0.4 VIf 9 UD(3V3)NIOHLOW-level short-circuit output currentV0L = VDD(3V3)If 9 UD(3V3)NIOHSHIGH-level short-circuit output currentV0L = VDD(3V3)If 9 UD(3V3)NIOHSLOW-level short-circuit output currentV0L = VDD(3V3)If 9 UD(3V3)15	Unit	Max	Typ <mark>[1]</mark>	Min		Conditions	Parameter	Symbol
Image: Intermediate interme							pins, RESET	Standard port
currentpull-down resistor disabled I_{OZ} OFF-state output current $V_0 = 0$, $V_0 = V_{D[03V3)}$; on-chip pull-u/down resistors disabled-3 V_i input voltagepin configured to provide a digital function $I2I(13)$ (14)0-5.0 V_0 output voltageoutput active0- $V_{DD(03V3)}$ voltage0- V_{IH} HIGH-level input voltage0.8V V_{IL} LOW-level input voltage0.8V V_{VH} HIGH-level output voltage $I_{OH} = -4$ mA151 voltageV V_{OL} LOW-level output current $I_{OH} = -4$ mA151 voltageV I_{OL} LOW-level output current $I_{OH} = -4$ mA151 voltageV I_{OL} LOW-level output current $I_{OH} = V_{DD(3V3)} - 0.4$ V151 voltage I_{OL} LOW-level output current $V_{OH} = 0$ V151 voltage I_{OL} LOW-level short-circuit output current $V_{OL} = V_{DD(3V3)}$ 161 voltage </td <td>μA</td> <td>3</td> <td>-</td> <td>-</td> <td></td> <td></td> <td>LOW-level input current</td> <td>I_{IL}</td>	μA	3	-	-			LOW-level input current	I _{IL}
current on-chip pull-up/down sessions disabled V1 input voltage pin configured to provide [12]13] 0 - 5.0 N Vo output voltage output active 0 - VDD(3V3) N V1H HIGH-level input voltage output active 0 - 0.8 N V1L LOW-level input voltage - 0.4 - - N V0H hysteresis voltage 0.4 - - N N V0H voltage IoH = -4 mA 15 VD(D03V3) - - N V0L LOW-level output IoL = 4 mA 15 - - N N IoH voltage VOL = VDD(3V3) - 0.4 V 15 -4 - - N N IoH current VOL = 0.4 V 15 -4 - - N N IoL LOW-level output VOL = 0.4 V 15 4 - - - N N IoLS LOW-level short-circuit <	μA	3	-	-		pull-down resistor	-	IIH
Image: A digital function [14] Vo output voltage output active 0 - $V_{D[3V3]}$ V VIH HIGH-level input voltage 2.0 - - 0.8 V VIL LOW-level input voltage - - 0.8 V Vhys hysteresis voltage 0.4 - - 0.8 V VOH HIGH-level output voltage IoH = -4 mA 151 VDD(3V3) - - 0.8 V VOH HIGH-level output voltage IoH = -4 mA 151 VDD(3V3) - - - V V VOL LOW-level output voltage IoL = 4 mA 151 - - 0.4 V IoL LOW-level output voltage VOL = VDD(3V3) - 0.4 V 151 -4 - - r IoL LOW-level output current VOL = 0.4 V 151 -4 - - r IoL LOW-level output current VOL = 0.4 V 151 -4 - - - r IoLS UOW-level short-circuit output current </td <td>μΑ</td> <td>3</td> <td>-</td> <td>-</td> <td></td> <td>on-chip pull-up/down</td> <td></td> <td>I_{OZ}</td>	μΑ	3	-	-		on-chip pull-up/down		I _{OZ}
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	V	5.0	-	0		, , ,	input voltage	VI
voltage voltage - - 0.8 V V _L LOW-level input voltage - 0.4 - - 0.8 V V _{DH} hysteresis voltage 0.4 - - 0.8 V V _{OH} HIGH-level output voltage $I_{OH} = -4 \text{ mA}$ 15 $V_{DD(3V3)} =$ - - - - - N V _{OL} LOW-level output voltage $I_{OL} = 4 \text{ mA}$ 15 - - 0.4 N N I_{OH} LOW-level output voltage $I_{OL} = 4 \text{ mA}$ 15 - - 0.4 N I_{OH} LOW-level output current $V_{OH} = V_{DD(3V3)} - 0.4 V$ 15 -4 - - - n I_{OL} LOW-level short-circuit current $V_{OL} = 0 V$ 15 4 - - - n I_{OLS} LOW-level short-circuit output current $V_{OL} = V_{DD(3V3)}$ 16 - - 50 n I_{pu} pull-down current $V_1 = 5 V$ 10 50 - 30 30 </td <td>V</td> <td>V_{DD(3V3)}</td> <td>-</td> <td>0</td> <td></td> <td>output active</td> <td>output voltage</td> <td>Vo</td>	V	V _{DD(3V3)}	-	0		output active	output voltage	Vo
V _{hys} hysteresis voltage 0.4 - - V V _{OH} HIGH-level output voltage I _{OH} = -4 mA 15 V _{DD(3V3)} - - - V V _{OL} LOW-level output voltage I _{OL} = 4 mA 15 - - 0.4 V I _{OH} LOW-level output voltage I _{OL} = 4 mA 15 - - 0.4 V I _{OH} HIGH-level output current V _{OL} = 0.4 V 15 -4 - - r I _{OL} LOW-level output current V _{OL} = 0.4 V 15 4 - - r I _{OL} LOW-level output current V _{OL} = 0.4 V 15 4 - - r I _{OL} LOW-level short-circuit output current V _{OL} = 0 V 16 - - -45 r I _{DL} pull-down current V _I = 5 V 10 50 15 10 10 I _{pu} pull-up current V _I = 0 V -15 -50 -85 10 <td>V</td> <td>-</td> <td>-</td> <td>2.0</td> <td></td> <td></td> <td>-</td> <td>V_{IH}</td>	V	-	-	2.0			-	V _{IH}
Vol HiGH-level output voltage $I_{OH} = -4 \text{ mA}$ 15 $V_{DD(3V3)} -$ - . N Vol LOW-level output voltage $I_{OL} = 4 \text{ mA}$ 15 - - 0.4 N IoH LOW-level output voltage $I_{OL} = 4 \text{ mA}$ 15 - - 0.4 N IoH HIGH-level output current $V_{OL} = 4 \text{ mA}$ 15 - - 0.4 N IoH HIGH-level output current $V_{OL} = 4 \text{ mA}$ 15 - - 0.4 N IoH HIGH-level output current $V_{OL} = V_{DD(3V3)} - 0.4 \text{ V}$ 15 -4 - - - r IoL LOW-level output current $V_{OL} = 0.4 \text{ V}$ 15 4 - - - r IoHS HIGH-level short-circuit output current $V_{OL} = V_{DD(3V3)}$ 16 - - -45 r IoLS LOW-level short-circuit lpu $V_{I} = 5 \text{ V}$ 10 50 150 p Ipu pull-down current $V_{I} = 5 \text{ V}$ 0 0 0	V	0.8	-	-			LOW-level input voltage	VIL
voltage 0.4 VoL LOW-level output voltage IoL = 4 mA [15] - - 0.4 N IoH HIGH-level output current V _{OH} = V _{DD(3V3)} - 0.4 V [15] - - 0.4 N IoH HIGH-level output current V _{OH} = V _{DD(3V3)} - 0.4 V [15] -4 - - r IoL LOW-level output current V _{OL} = 0.4 V [15] 4 - - r IoHS HIGH-level short-circuit output current V _{OL} = 0.4 V [16] - - - - r IoHS HIGH-level short-circuit output current V _{OL} = 0.4 V [16] - 50 r r - - 50 r - - 50 r 1 1 - -	V	-	-	0.4			hysteresis voltage	V _{hys}
Voltage Voltage VOL VOH VOH VOH Image VOH Image Ima<	V	-	-		[15]	$I_{OH} = -4 \text{ mA}$	-	V _{OH}
our and currentcurrentCurre	V	0.4	-	-	[15]	$I_{OL} = 4 \text{ mA}$	•	V _{OL}
currentIOHSHIGH-level short-circuit output current $V_{OH} = 0 V$ $\begin{bmatrix} 16 \\ 16 \end{bmatrix}$ 45rIOLSLOW-level short-circuit output current $V_{OL} = V_{DD(3V3)}$ $\begin{bmatrix} 16 \\ 16 \end{bmatrix}$ 50rIpdpull-down current $V_1 = 5 V$ 1050150pIpupull-up current $V_1 = 0 V$ -15-50-85pOscillator pinsVi = 0 V000pVi(XTAL1)input voltage on pin XTAL1-0.51.81.95V	mA	-	-	-4	[15]	$V_{OH} = V_{DD(3V3)} - 0.4 \ V$	-	I _{OH}
Initial output currentVolt of the transformed and transforme	mA	-	-	4	[15]	$V_{OL} = 0.4 V$		I _{OL}
output current $V_1 = 5 V$ 10 50 150 μ I_{pu} pull-down current $V_1 = 5 V$ 10 50 150 μ I_{pu} pull-up current $V_1 = 0 V$ -15 -50 -85 μ Oscillator pins $V_{DD(3V3)} < V_1 < 5 V$ 0 0 0 μ $V_{i(XTAL1)}$ input voltage on pin XTAL1 -0.5 1.8 1.95 V_{i}	mA	-45	-	-	<u>[16]</u>	V _{OH} = 0 V		I _{OHS}
$\begin{array}{c c c c c c c c c c } \hline I_{pu} & pull-up \ current & V_{I} = 0 \ V & -15 & -50 & -85 & \mu \\ \hline V_{DD(3V3)} < V_{I} < 5 \ V & 0 & 0 & 0 & \mu \\ \hline \textbf{Oscillator pins} & & & & \\ \hline V_{i(XTAL1)} & input \ voltage \ on \ pin \\ XTAL1 & & & & & \\ \hline \end{array}$	mA	50	-	-	[16]	$V_{OL} = V_{DD(3V3)}$		I _{OLS}
VDD(3V3) < VI < 5 V 0	μA	150	50	10		$V_I = 5 V$	pull-down current	I _{pd}
Oscillator pins V _{i(XTAL1)} input voltage on pin -0.5 1.8 1.95 V XTAL1	μA	-85	-50	–15		-	pull-up current	I _{pu}
V _{i(XTAL1)} input voltage on pin XTAL1 –0.5 1.8 1.95 V	μA	0	0	0		$V_{DD(3V3)} < V_{I} < 5 V$		
XTAL1							S	Oscillator pins
V_{-} (V_A) = 0.5 1.8 1.95 V	V	1.95	1.8	-0.5				V _{i(XTAL1)}
XTAL2) XTAL2	V	1.95	1.8	-0.5			output voltage on pin XTAL2	V _{o(XTAL2)}
V _{i(RTCX1)} input voltage on pin -0.5 1.8 1.95 N RTCX1	V	1.95	1.8	-0.5				V _{i(RTCX1)}
V _{o(RTCX2)} output voltage on pin RTCX2 -0.5 1.8 1.95 V	V	1.95	1.8	-0.5				V _{o(RTCX2)}



32-bit ARM Cortex-M3 microcontroller

Table 6. Static characteristics ...continued

 $T_{amb} = -40$ °C to +85 °C, unless otherwise specified.

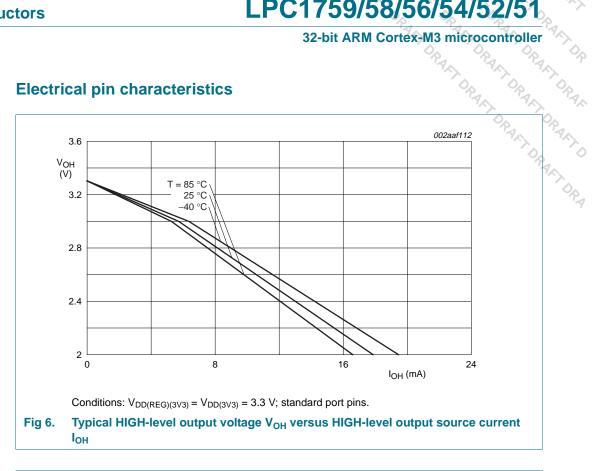
Symbol	Parameter	Conditions	Min	Typ <mark>[1]</mark>	Max	Unit 🔮
USB pins						1 AN
I _{OZ}	OFF-state output current	0 V < V _I < 3.3 V	-	-	±10	μA
V _{BUS}	bus supply voltage		-	-	5.25	V
V _{DI}	differential input sensitivity voltage	(D+) – (D–)	0.2	-	-	V
V _{CM}	differential common mode voltage range	includes V_{DI} range	0.8	-	2.5	V
V _{th(rs)se}	single-ended receiver switching threshold voltage		0.8	-	2.0	V
V _{OL}	LOW-level output voltage for low-/full-speed	R_L of 1.5 k Ω to 3.6 V	-	-	0.18	V
V _{OH}	HIGH-level output voltage (driven) for low-/full-speed	R_L of 15 $k\Omega$ to GND	2.8	-	3.5	V
C _{trans}	transceiver capacitance	pin to GND	-	-	20	pF
Z _{DRV}	driver output impedance for driver which is not high-speed capable	with 33 Ω series resistor; steady state drive	[<u>17]</u> 36	-	44.1	Ω

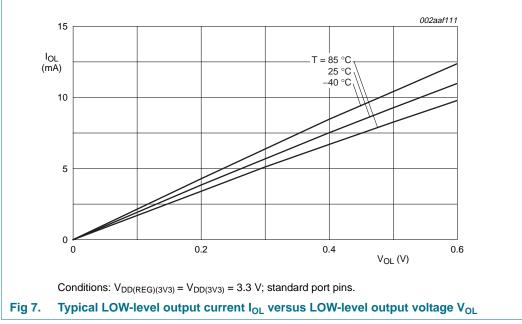
[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

- [2] The RTC typically fails when $V_{i(VBAT)}$ drops below 1.6 V.
- [3] $V_{DD(REG)(3V3)} = 3.3 \text{ V}$; $T_{amb} = 25 \text{ °C}$ for all power consumption measurements.
- [4] LPC1759 only.
- [5] IRC running at 4 MHz; main oscillator and PLL disabled; PCLK = CCLK/8.
- [6] BOD disabled.
- [7] On pin VBAT. I_{DD(REG)(3V3)} = 520 nA. V_{DD(REG)(3V3)} = 3.3 V; V_{BAT} = 3.3 V. T_{amb} = 25 °C.
- [8] On pin VBAT. $V_{BAT} = 3.3 \text{ V}$. $T_{amb} = 25 \text{ °C}$.
- [9] All internal pull-ups disabled. All pins configured as output and driven LOW. V_{DD(3V3)} = 3.3 V; T_{amb} = 25 °C.
- [10] $V_{DDA} = 3.3 \text{ V}$; $T_{amb} = 25 \text{ °C}$.
- [11] $V_{i(VREFP)} = 3.3 \text{ V}; \text{ T}_{amb} = 25 \ ^{\circ}\text{C}.$
- [12] Including voltage on outputs in 3-state mode.
- [13] V_{DD(3V3)} supply voltages must be present.
- [14] 3-state outputs go into 3-state mode in Deep power-down mode.
- [15] Accounts for 100 mV voltage drop in all supply lines.
- [16] Allowed as long as the current limit does not exceed the maximum current allowed by the device.
- [17] Includes external resistors of 33 $\Omega\pm$ 1 % on D+ and D–.

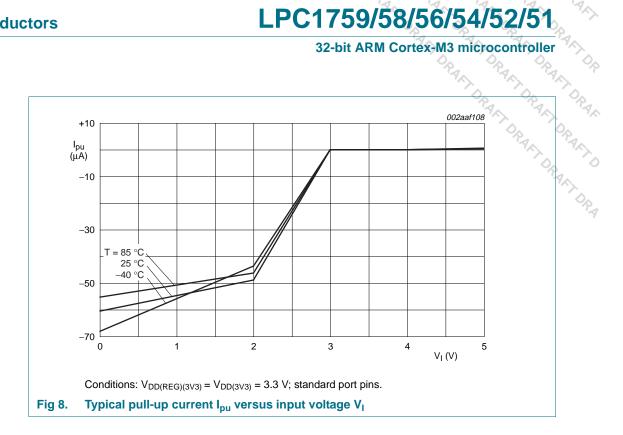
32-bit ARM Cortex-M3 microcontroller

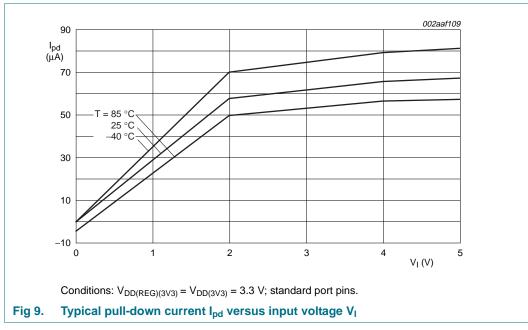
10.1 Electrical pin characteristics





32-bit ARM Cortex-M3 microcontroller





11. Dynamic characteristics

11.1 Flash memory

Table 7. **Flash characteristics**

NXP Sem	iconductors		LPC	:1759)/58/5	56/54/	52/51
				32-bit A	RM Corte	x-M3 micro	controller
11. Dyn	amic characte	ristics				P.S.	A A A A A A A A A A A A A A A A A A A
	11.1 Flash m	emory					RAL RAN
	Hash characteristics C to +85 ℃, unless othe	erwise specified.					RAND
Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
N _{endu}	endurance		<u>[1</u>	<mark>1</mark> 10000	-	-	cycles
t _{ret}	retention time	powered		10	-	-	years
		unpowered		20	-	-	years

[1] Number of program/erase cycles.

11.2 External clock

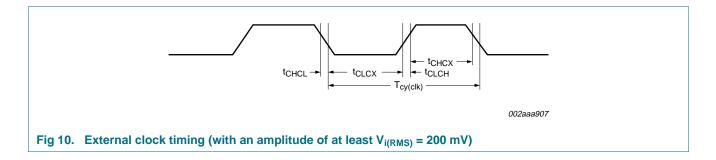
Dynamic characteristic: external clock Table 8.

 $T_{amb} = -40 \ ^{\circ}C$ to +85 $^{\circ}C$; $V_{DD(3V3)}$ over specified ranges.[1]

Symbol	Parameter	Conditions	Min	Typ <mark>[2]</mark>	Max	Unit
f _{osc}	oscillator frequency		1	-	25	MHz
T _{cy(clk)}	clock cycle time		40	-	1000	ns
t _{CHCX}	clock HIGH time		$\rm T_{cy(clk)} \times 0.4$	-	-	ns
t _{CLCX}	clock LOW time		$\rm T_{cy(clk)} \times 0.4$	-	-	ns
t _{CLCH}	clock rise time		-	-	5	ns
t _{CHCL}	clock fall time		-	-	5	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages. [2]



11.3 Internal oscillators

Table 9. Dynamic characteristic: internal oscillators

```
T_{amb} = -40 \ ^{\circ}C \ to +85 \ ^{\circ}C; 2.7 \ V \leq V_{DD(3V3)} \leq 3.6 \ V.^{[1]}
```

					~P.	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	\$
			32-bit A	RM Cortex-M	3 microo	controller	A.
				0	PAR O	PAN PA	90 10
	11.3 Internal oscillators				DRA	Op A	DRAN
	Dynamic characteristic: internal oscill C to +85 °C; 2.7 V \leq V _{DD(3V3)} \leq 3.6 V.[1]	ators				DRAN	OPAN
Symbol	Parameter	Conditions	Min	Typ <mark>[2]</mark>	Max	Unit	6
f _{osc(RC)}	internal RC oscillator frequency	-	3.96	4.00	4.04	MHz	PAL A
f _{i(RTC)}	RTC input frequency	-	-	32.768	-	kHz	Op

Parameters are valid over operating temperature range unless otherwise specified. [1]

Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages. [2]

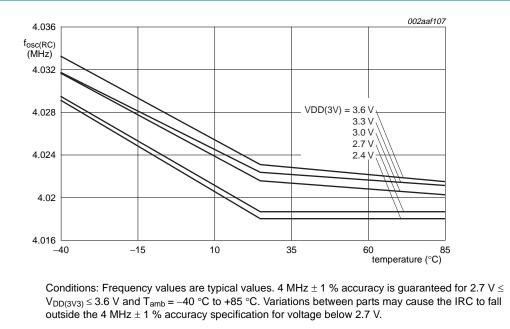


Fig 11. Internal RC oscillator frequency versus temperature

11.4 I/O pins

Table 10. Dynamic characteristic: I/O pins^[1]

 $T_{amb} = -40 \ ^{\circ}C$ to +85 $^{\circ}C$; $V_{DD(3V3)}$ over specified ranges.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _r	rise time	pin configured as output	3.0	-	5.0	ns
t _f	fall time	pin configured as output	2.5	-	5.0	ns

[1] Applies to standard port pins and RESET pin.

11.5 I²C-bus interface

Table 11. Dynamic characteristic: I²C-bus pins (Fast-mode Plus)

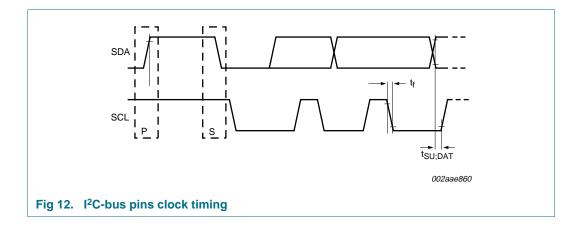
 $T_{amb} = -40 \text{ °C to } +85 \text{ °C}; V_{DD(3V3)} \text{ over specified ranges.}$

			32-bit A	ARM Cortex-I	M3 microo	controlle	1 9. 1.
	11.5 I ² C-bus interfac	e			OP4	^C D _P A	10A
						`入 ``)	7
	Dynamic characteristic: I^2C -bus p C to +85 °C; $V_{DD(3V3)}$ over specified					OPAN	OPAN
			Min	Тур	Max	Unit	Opq AP
୮ _{amb} = −40 ବ Symbol	C to +85 °C; $V_{DD(3V3)}$ over specified	d ranges.[1][2][3]	Min -	Typ -	Max 1	Unit MHz	ORAK, AK,
$T_{amb} = -40$ °	C to +85 °C; V _{DD(3V3)} over specified Parameter	d ranges.[1][2][3]	Min - -	Тур - -	Max 1 45		DRAK, ARTO,

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] CCLK = PCLK = 20 MHz; I²C-bus interface configured in master mode.

[3] Bus capacitance C_b in pF (50 pF), external pull-up resistance = 218 Ω .

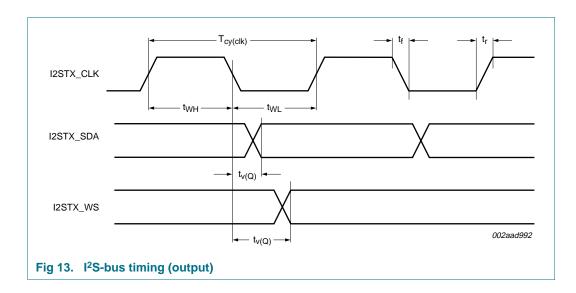


11.6 I²S-bus interface (LPC1759/58/56 only)

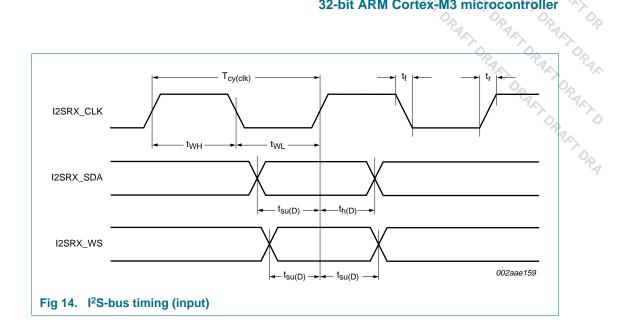
Table 12. Dynamic characteristics: I²S-bus interface pins

NXP Se	emiconductors			PC1759	/58/	56/54/5	2/51
				32-bit AR	RM Cor	tex-M3 microco	ontroller
Table 12. T _{amb} = -40		interface (LPC1759/5 cs: I ² S-bus interface pins	8/56	only)		tex-M3 microco	NET DRAFT DR
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
common	to input and output						AV.
t _r	rise time		[1]	-	-	35	ns
t _f	fall time		[1]	-	-	35	ns
t _{WH}	pulse width HIGH	on pins I2STX_CLK and I2SRX_CLK	[1]	$0.495 \times T_{cy(clk)}$	-	-	-
t _{WL}	pulse width LOW	on pins I2STX_CLK and I2SRX_CLK	[1]	-	-	$0.505 \times T_{cy(clk)}$	ns
output							
t _{v(Q)}	data output valid time	on pin I2STX_SDA;	[1]	-	-	30	ns
		on pin I2STX_WS	[1]	-	-	30	ns
input							
t _{su(D)}	data input set-up time	on pin I2SRX_SDA	<u>[1]</u>	3.5	-	-	ns
t _{h(D)}	data input hold time	on pin I2SRX_SDA	[1]	4.0	-	-	ns

[1] CCLK = 20 MHz; peripheral clock to the I²S-bus interface PCLK = ^{CCLK}/₄; T_{cy(clk)} = 1600 ns, corresponds to the SCK signal in the I²S-bus specification.



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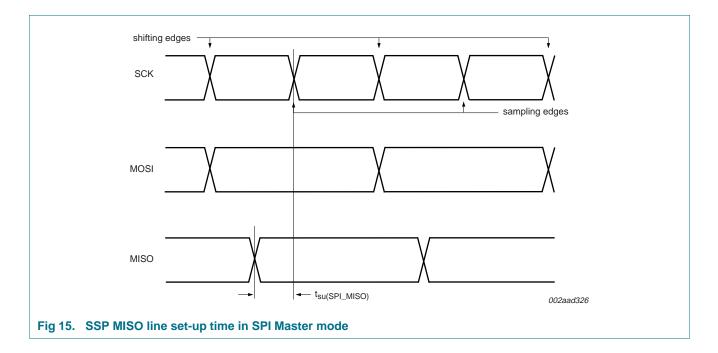
11.7 SSP interface

Table 13. Dynamic characteristic: SSP interface

$T_{amb} = 25 \ ^{\circ}C; V_{DD(3V3)}$ over specified rang

				~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~		7	Ϋ́ρ.
		32	2-bit ARM	Cortex-	M3 micro	controll	er
					PAR	P.A.	A A
	11.7 SSP interfac	e			ORA	-ORA	DRAD
	amic characteristic: SSP _{D(3V3)} over specified range					DRAN.	DRAN
Symbol	Parameter	Conditions	Min	Тур	Max	Unit	, 0
$t_{\text{su}(\text{SPI}_\text{MISO})}$	SPI_MISO set-up tim	e measured in SPI Master mode; see Figure 15	[ <u>1]</u> 30	-	-	ns	AV DO

[1] The peripheral clock for SSP is PCLK = CCLK = 20 MHz.

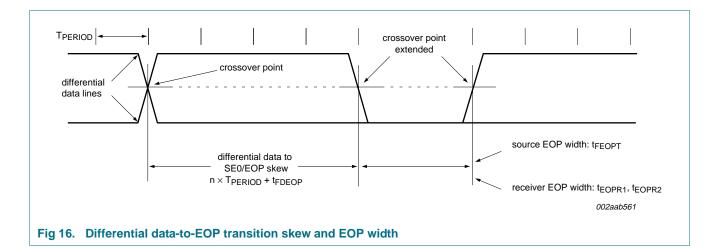


#### 11.8 USB interface

Table 14.	Dynamic	characteristics:	USB	pins	(full-speed)
-----------	---------	------------------	-----	------	--------------

NXP Semiconductors		LPC1/39/30/30/34/32/31					
			32-bit ARI	M Cortex-	M3 microc	ontrolle	r 🦘
	<b>11.8 USB interface</b> namic characteristics: USB pins (full-solution) $\mu = 1.5 k\Omega$ on D+ to $V_{DD(3V3)}$ , unless other				M3 microc	ACT DRAG	ALT DRAC
Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
t _r	rise time	10 % to 90 %	8.5	-	13.8	ns	AN
t _f	fall time	10 % to 90 %	7.7	-	13.7	ns	0
t _{FRFM}	differential rise and fall time matching	t _r / t _f	-	-	109	%	
V _{CRS}	output signal crossover voltage		1.3	-	2.0	V	
t _{FEOPT}	source SE0 interval of EOP	see Figure 16	160	-	175	ns	
t _{FDEOP}	source jitter for differential transition to SE0 transition	see Figure 16	-2	-	+5	ns	
t _{JR1}	receiver jitter to next transition		-18.5	-	+18.5	ns	
t _{JR2}	receiver jitter for paired transitions	10 % to 90 %	-9	-	+9	ns	
t _{EOPR1}	EOP width at receiver	must reject as EOP; see <u>Figure 16</u>	<u>[1]</u> 40	-	-	ns	
t _{EOPR2}	EOP width at receiver	must accept as EOP; see <u>Figure 16</u>	[1] 82	-	-	ns	

[1] Characterized but not implemented as production test. Guaranteed by design.



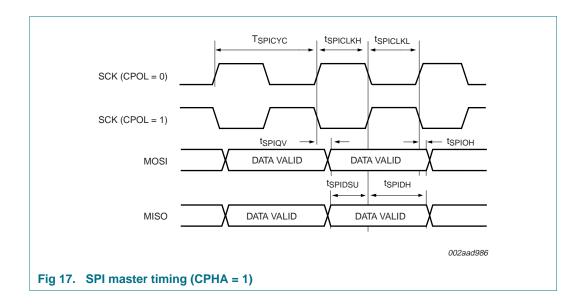
#### 11.9 SPI

#### Table 15. Dynamic characteristics of SPI pins

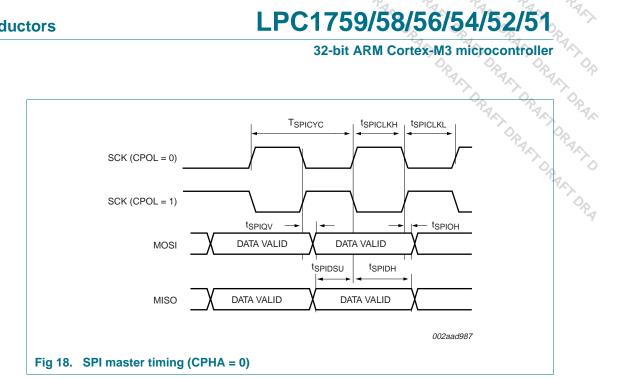
			32-bit ARI	VI Cort	ex-M3 microcol	Unit
SPI					OPA	Op 1
<b>Fable 15.</b> T _{amb} = -40	Dynamic characteristics o $^{\circ}C$ to +85 $^{\circ}C$ .	f SPI	pins		`^>\	PAR A
Symbol	Parameter		Min	Тур	Max	Unit
T _{cy(PCLK)}	PCLK cycle time		10	-	-	ns
T _{SPICYC}	SPI cycle time	[1]	79.6	-	-	ns
t _{SPICLKH}	SPICLK HIGH time		$0.485 \times T_{\text{SPICYC}}$	-	-	ns
t _{SPICLKL}	SPICLK LOW time			-	$0.515 \times T_{\text{SPICYC}}$	ns
SPI maste	r					
t _{SPIDSU}	SPI data set-up time	[2]	0	-	-	ns
t _{SPIDH}	SPI data hold time	[2]	$2\times T_{cy(PCLK)}-5$	-	-	ns
t _{SPIQV}	SPI data output valid time	[2]	$2 \times T_{cy(PCLK)}$ + 30	-	-	ns
t _{SPIOH}	SPI output data hold time	[2]	$2 \times T_{cy(PCLK)}$ + 5	-	-	ns
SPI slave						
t _{SPIDSU}	SPI data set-up time	[2]	0	-	-	ns
t _{SPIDH}	SPI data hold time	[2]	$2 \times T_{cy(PCLK)}$ + 5	-	-	ns
t _{SPIQV}	SPI data output valid time	[2]	$2 \times T_{cy(PCLK)}$ + 35	-	-	ns
t _{SPIOH}	SPI output data hold time	[2]	$2 \times T_{cy(PCLK)}$ + 15	_		ns

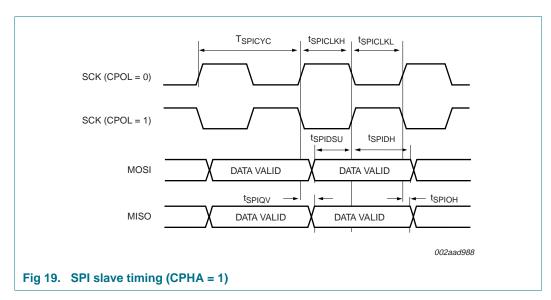
 $[1] \quad T_{SPICYC} = (T_{cy(PCLK)} \times n) \pm 0.5 \ \text{\%}, \ n \ \text{is the SPI clock divider value } (n \geq 8); \ PCLK \ \text{is derived from the}$ processor clock CCLK.

Timing parameters are measured with respect to the 50 % edge of the clock PCLK and the 10 % (90 %) [2] edge of the data signal (MOSI or MISO).

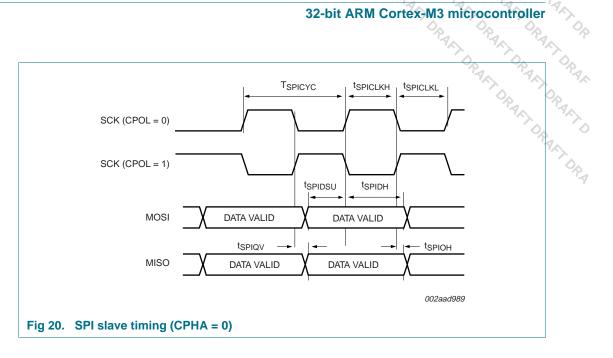


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32-bit ARM Cortex-M3 microcontroller



#### 12. ADC electrical characteristics

#### Table 16. ADC characteristics

V_{DDA} = 2.7 V to 3.6 V; T_{amb} = −40 °C to +85 °C unless otherwise specified; ADC frequency 13 MHz.

DBM	, and		,	,	,		
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
VIA	analog input voltage			0	-	V _{DDA}	V
C _{ia}	analog input capacitance			-	-	15	pF
E _D	differential linearity error		<u>[1][2][3]</u>	-	-	±1	LSB
E _{L(adj)}	integral non-linearity		<u>[1][4]</u>	-	-	±3	LSB
Eo	offset error		<u>[1][5]</u>	-	±2	-	LSB
E _G	gain error		<u>[1][6]</u>	-	-	0.5	%
Ε _T	absolute error		<u>[1][7]</u>	-	-	4	LSB
R _{vsi}	voltage source interface resistance		[8]	-	-	7.5	kΩ
f _{clk(ADC)}	ADC clock frequency			-	-	13	MHz
f _{c(ADC)}	ADC conversion frequency			-	-	200	kHz

[1] Conditions:  $V_{SSA} = 0 V$ ,  $V_{DDA} = 3.3 V$ .

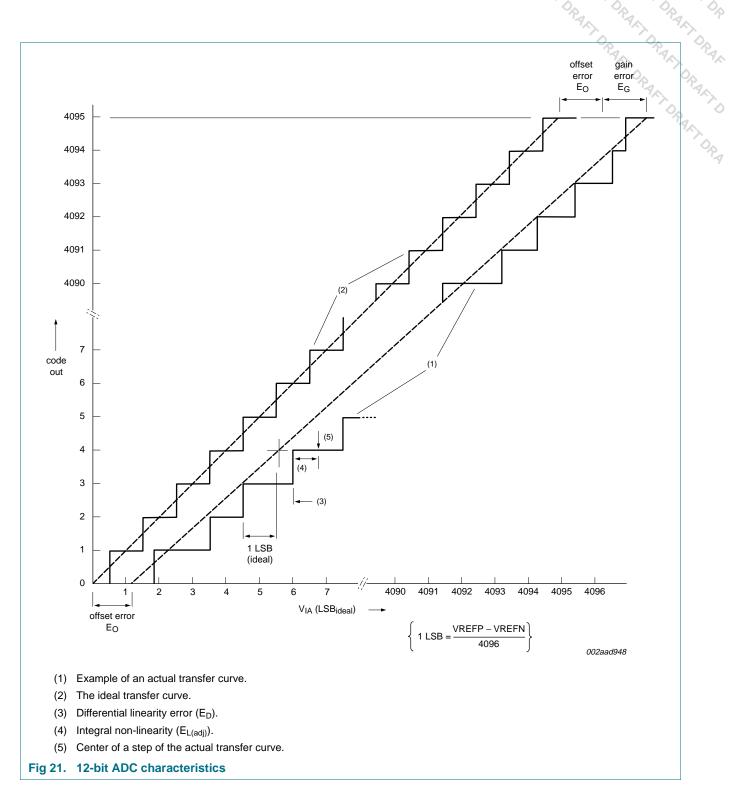
[2] The ADC is monotonic, there are no missing codes.

[3] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 21.

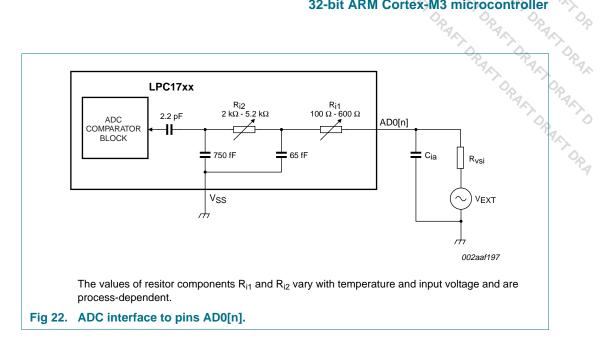
- The integral non-linearity (E_{L(adj)}) is the peak difference between the center of the steps of the actual and the ideal transfer curve after [4] appropriate adjustment of gain and offset errors. See Figure 21.
- The offset error (E_D) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the [5] ideal curve. See Figure 21.
- [6] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 21.
- The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated [7] ADC and the ideal transfer curve. See Figure 21.

See Figure 22. [8]

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#### 13. DAC electrical characteristics (LPC1759/58/56/54 only)

#### Table 17. DAC electrical characteristics

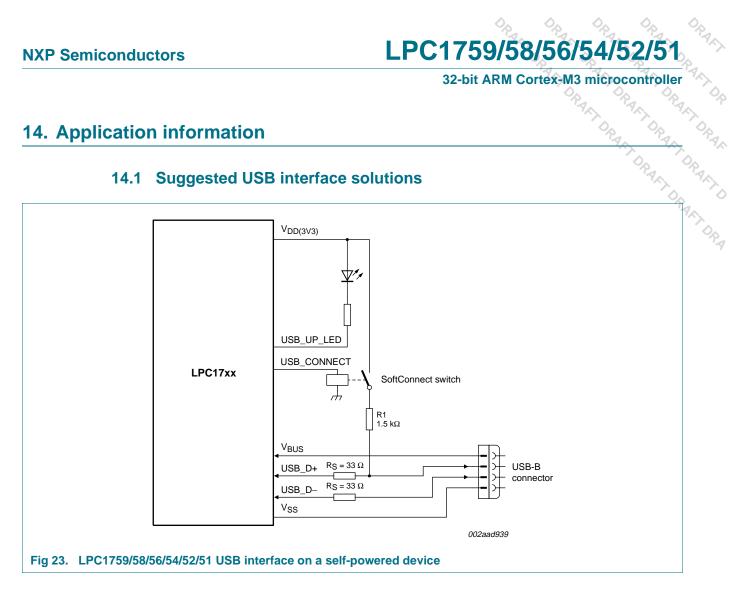
 $V_{DDA}$  = 2.7 V to 3.6 V;  $T_{amb}$  = -40 °C to +85 °C unless otherwise specified

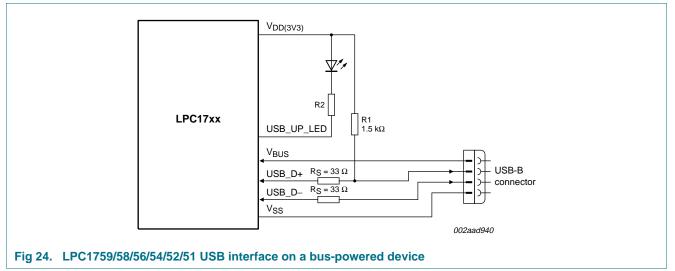
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
E _D	differential linearity error		-	±1	-	LSB
E _{L(adj)}	integral non-linearity		-	±1.5	-	LSB
E _O	offset error		-	0.6	-	%
E _G	gain error		-	0.6	-	%
CL	load capacitance		-	200	-	pF
RL	load resistance		1	-	-	kΩ

32-bit ARM Cortex-M3 microcontroller

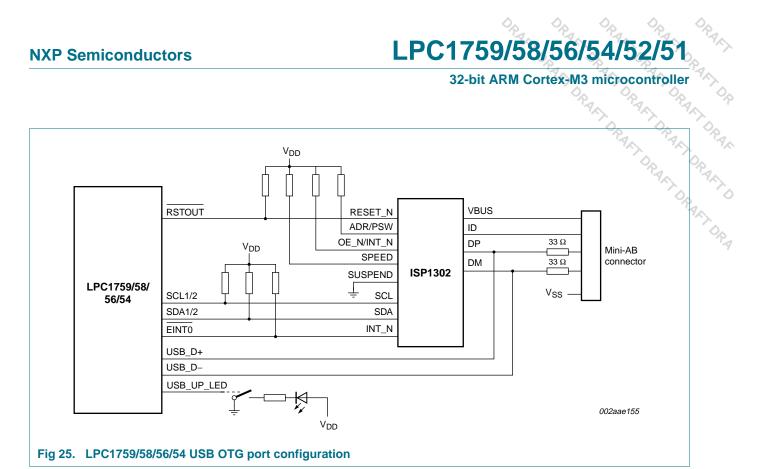
#### 14. Application information

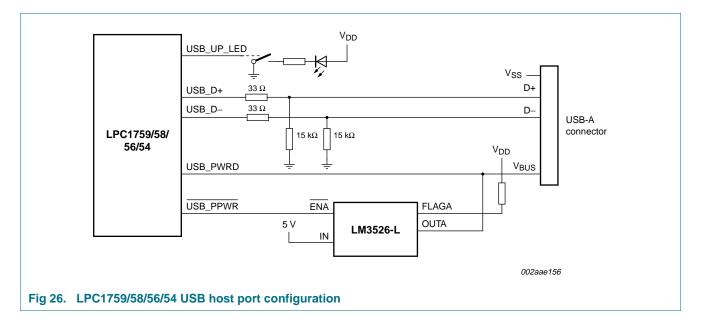
#### 14.1 Suggested USB interface solutions



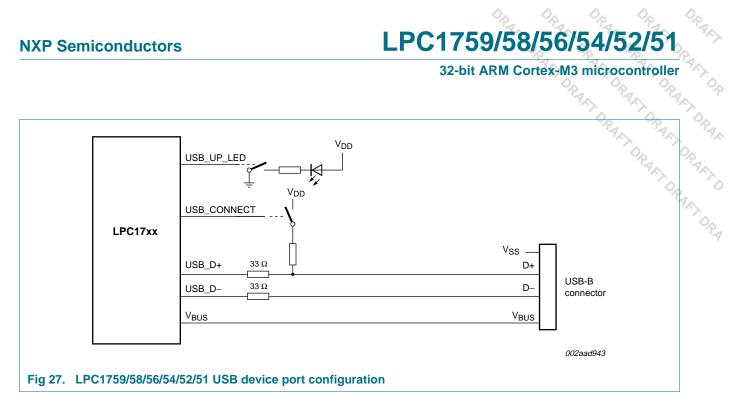


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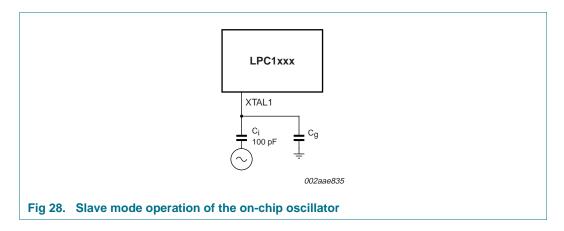


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#### 14.2 XTAL1 input

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with  $C_i = 100 \text{ pF}$ . To limit the input voltage to the specified range, choose an additional capacitor to ground  $C_{\alpha}$  which attenuates the input voltage by a factor  $C_i/(C_i + C_{\alpha})$ . In slave mode, a minimum of 200 mV (RMS) is needed. For more details see the LPC17xx User manual.



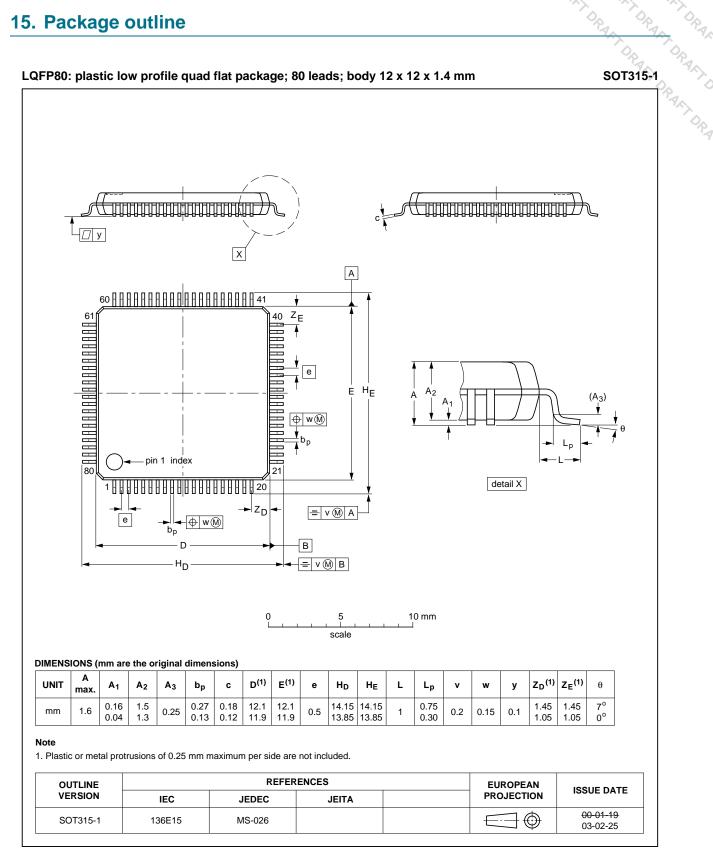
#### 14.3 XTAL and RTCX Printed Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors Cx1,Cx2, and Cx3 in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plain. Loops must be made as small as possible in order to keep the noise coupled in via the PCB as small as possible. Also parasitics should stay as small as possible. Values of  $C_{x1}$  and  $C_{x2}$  should be chosen smaller accordingly to the increase in parasitics of the PCB layout.



32-bit ARM Cortex-M3 microcontroller A. ORACT DRA DRAKT DRA

#### 15. Package outline



#### Fig 29. Package outline (LQFP80)

LPC1759_58_56_54_52_51_3

## LPC1759/58/56/54/52/51 32-bit ARM Cortex-M3 microcontroller

#### 16. Abbreviations

32-bit ARM Cortex-M3 mic	PAR
	rocontrolle Randa Randa
e 18. Abbreviations	Dp.
onym Description	7
C Analog-to-Digital Converter	
Advanced High-performance Bus	
Advanced Microcontroller Bus Architecture	
Advanced Peripheral Bus	
D BrownOut Detection	
Controller Area Network	
Digital-to-Analog Converter	
Debug Communication Channel	
A Direct Memory Access	
Digital Signal Processing	
P End Of Packet	
Embedded Trace Macrocell	
O General Purpose Input/Output	
Internal RC	
Infrared Data Association	
G Joint Test Action Group	
C Media Access Control	
Media Independent Interface Management	
G On-The-Go	
Physical Layer	
Phase-Locked Loop	
M Pulse Width Modulator	
Reduced Media Independent Interface	
Single Ended Zero	
Serial Peripheral Interface	
Serial Synchronous Interface	
Synchronous Serial Port	
Transistor-Transistor Logic	
T Universal Asynchronous Receiver/Transmitter	
Universal Serial Bus	

#### 17. Revision history

			1759/58/56/54/52/5
			32-bit ARM Cortex-M3 microcontro
			AN ANY
17. Revision history			OP AN ON
Table 19. Revision history			Change Supersedes
Document ID	Release date	Data sheet status	enange enpereene
DC171750 50 50 54 50 51 2 02	th de	Draduct data aboat	
_PC171759_58_56_54_52_51_3.03	<tbd></tbd>	Product data sheet	LPC1759_58_56_54_52_51 3.02
Modifications:	Feature list corr	ected: LPC1759 does no	t support Ethernet.
_PC171759_58_56_54_52_51_3.02	<tbd></tbd>	Product data sheet	LPC1759_58_56_54_52_51
			3.01
Modifications:	<ul> <li>Moved para</li> </ul>	ameters t _r and t _f from <u>Tab</u>	le 6 to Section 11.4.
	<ul> <li>ADC static</li> </ul>	characteristics: Parameter	er R _{vsi} and <u>Figure 22</u> added.
	<ul> <li>Table note</li> </ul>	14 in <u>Table 6</u> updated.	
	<ul> <li>In <u>Table 6</u> r</li> </ul>	move parameter V _{hys} valu	e from typical to minimum.
_PC171759_58_56_54_52_51_3.01	<tbd></tbd>	Product data sheet	LPC1758_56_54_52_51_3
Aodifications:	<ul> <li>Added part</li> </ul>	LPC1759.	
	<ul> <li>Added para</li> </ul>	ameters t _r and t _f for outpu	t pins in <u>Table 6</u> .
	<ul> <li>Added SRA</li> </ul>	AM sizes for CPU SRAM,	AHB SRAM0, and AHB SRAM1 in Table
	<ul> <li>Added table</li> </ul>	e note for XTAL1 and XT	AL2 pins in <u>Table 3</u> .
PC1758_56_54_52_51_3	20091119	Product data sheet	- LPC1758_56_54_52_51_2
lodifications:	Added Elect	ctrical pin characteristics	
		ata sheet status to Produ	
	•	data bit rate for SPI, SSP,	
		up RAM size updated (20	
		source added: RTC osci	
		ersion rate changed to 20	
		symbols from timing diagr	
		otor control PWM pin nan	nes in Table 3 "Pin description" and Figure
	<ul> <li>ENET_MD (<u>Table 3</u>).</li> </ul>	C and ENET_MDIO funct	tions removed from pin P2[8] and P2[9]
	<ul> <li>V_{DDA} and V</li> </ul>	REFP pin descriptions u	pdated ( <u>Table 3</u> ).
	<ul> <li>CLKOUT full</li> </ul>	unction removed (Table 3	).
	<ul> <li>V_{esd} chang</li> </ul>	ed to $\pm$ 4000 V (Table 4).	
		sumption data added to	able 6.
	<ul> <li>Flash chara</li> </ul>	acteristics table updated	(Table 7).
		ing characteristics added	
		characteristics added (Ta	
	-	ute error E _T added (Table	
		ical characteristics updat	
		uit and PCB layout recon	mendations added (see <u>Section 14.2</u> an
			n Table 16 "ADC characteristics".)
LPC1758_56_54_52_51_2	20090211	Objective data sheet	- LPC1758_56_54_52_51_1

# LPC1759/58/56/54/52/51 32-bit ARM Cortex-M3 microcontroller

Table 19. Revision history cor	linuea			P	P P
Document ID	Release date	Data sheet status	Change Supersedes notice		Op
Modifications:	•	ash characteristics. gure 3 "LPC1758/56/54/	52/51 memory map".		AT DRAK
LPC1758_56_54_52_51_1	20090115	Objective data sheet			OP-

#### Table 19 Revision history continued

#### **18. Legal information**

#### 18.1 Data sheet status

NXP Semiconduc	tors	LPC1759/58/56/54/52/51
		32-bit ARM Cortex-M3 microcontroller
18. Legal infor	mation	DRA DRA DRA
18.1 Data sheet	status	DRACT-DRACT
Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

Please consult the most recently issued document before initiating or completing a design. [1]

[2] The term 'short data sheet' is explained in section "Definitions".

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Document identifier: LPC1759_58_56_54_52_51_3

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